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MAIN ANT

MAIN1-1 ANT

MAIN1-2 ANT

MAIN4 ANT

MAIN2 ANT

M1-1

M4

M1-2

M2

M3

MAIN3 ANT

FRC connector

JPN

LTE\_B21

2G\_PA

THERMISTER

LB LPAMID  
(B5/8/12/13/14/17/20/26/28/29/71, G850/900, BC0/10)

OMH LPAMID  
(B1/2/3/4/7/25/30/34/38/39/40/41/66, G1800/1900, BC1)

UHB  
(B48, n77/78/79)

ET Modulator(QET5100#0)

ET Modulator(QET5100#1)

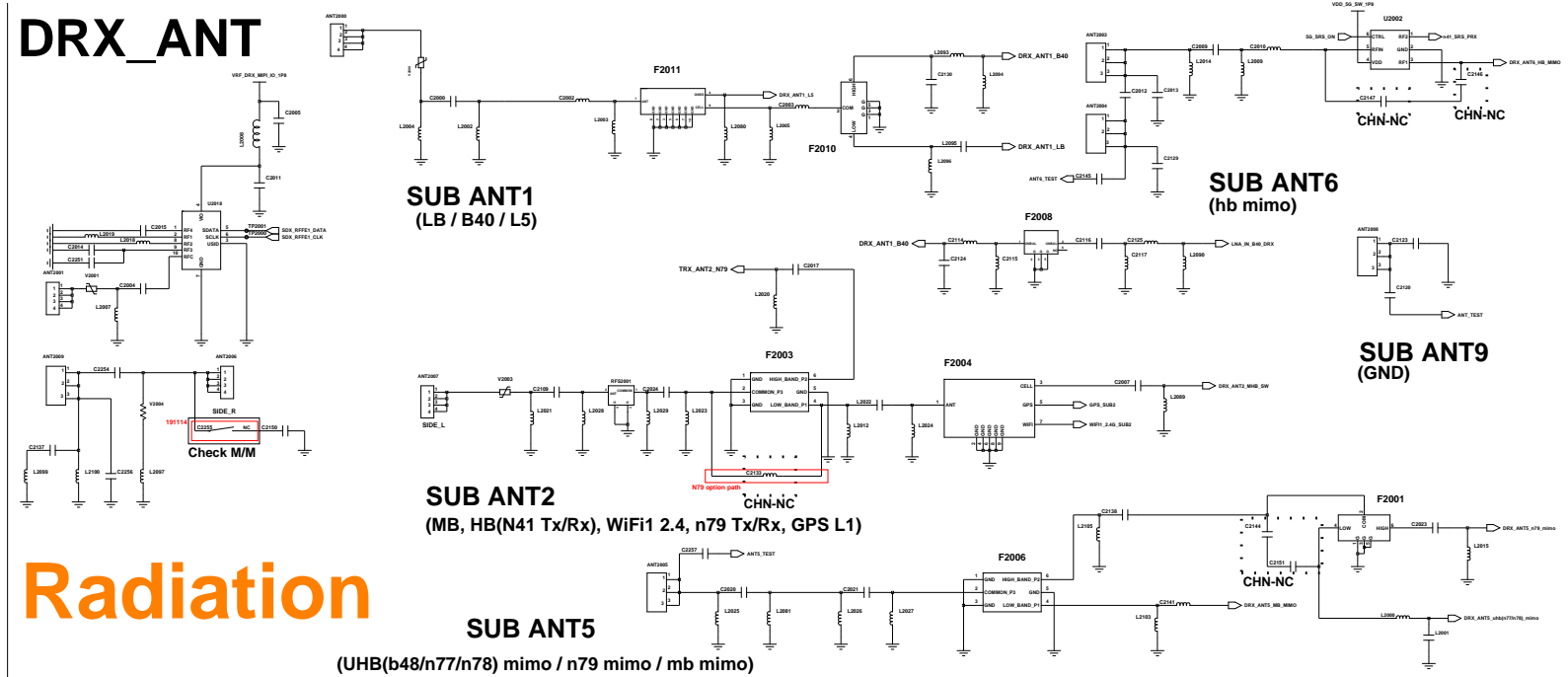


Engineer:	SEC		
Drawn by:	SEC		
Check Date:		TITLE:	Sheet
Doc. Title Code:			
Rev Model Code:			
QA CRE:			
	REV:	Drawing Number:	

Change by:      Date Changed:      Time Changed:      QA Date:      Rev:

# TRANSCEIVER(SDR865)

## DRX\_ANT

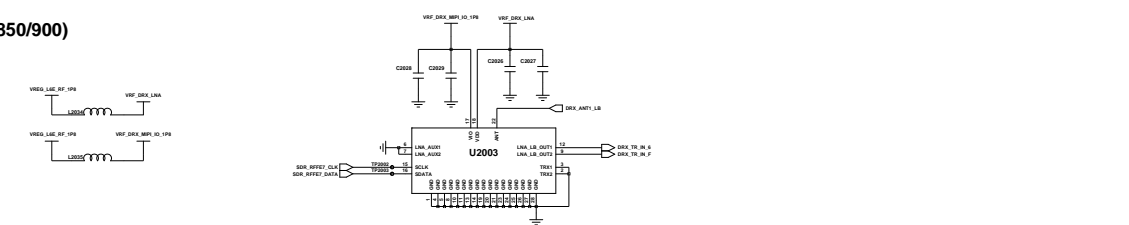


## Radiation

### DRX\_LB

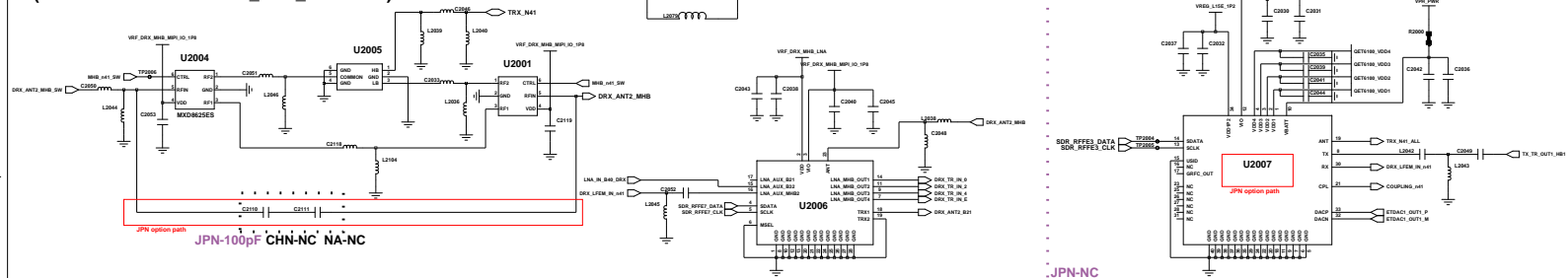
(B5/8/12/13/14/17/18/19/20/26/28/29/71\_BC0/10\_G850/900)

## Conduction



### DRX\_MHB\_1

(B1/2/3/4/7/25/30/39/41/66\_BC1\_DCS/PCS)

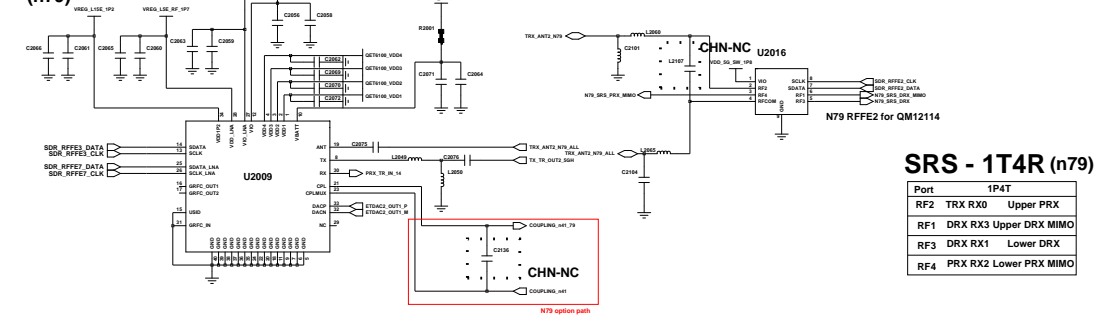


### DRX\_MHB\_2

(B2/4/7/25/30/41/66)

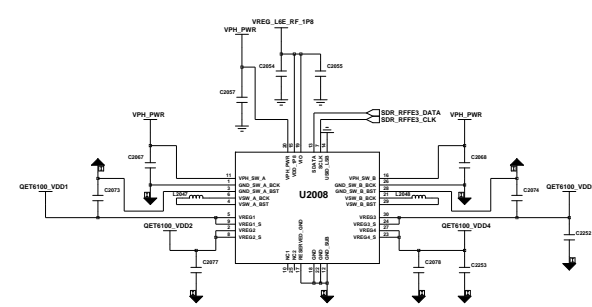
### UHB

(n79)



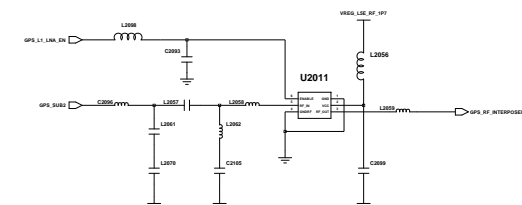
## Conduction

### QET6100

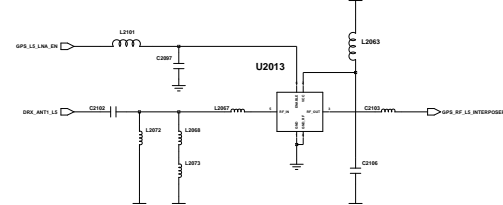


## Connectivity

### GPS\_L1

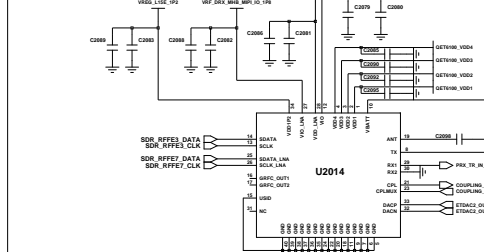


### GPS\_L5



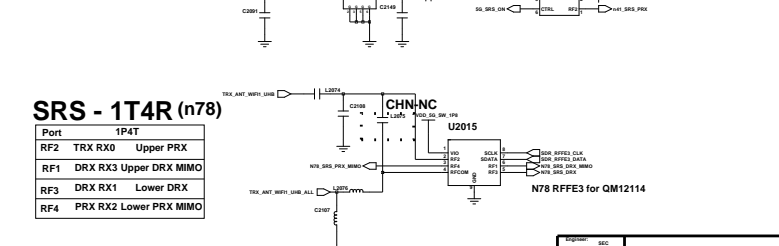
### UHB

(B48, n77/78)



### SRS - 1T2R

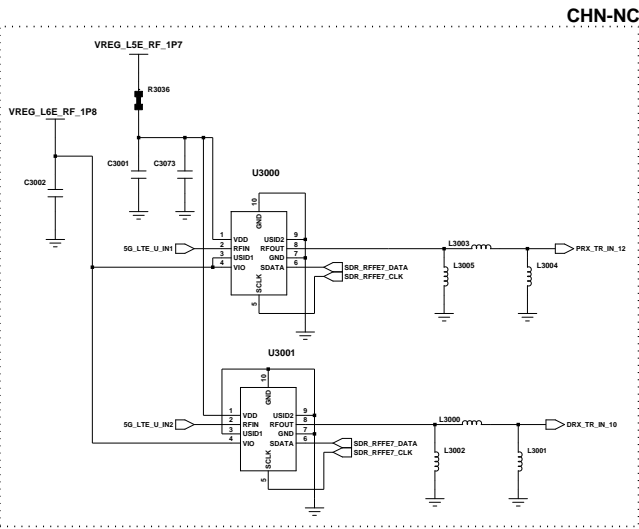
(n41)



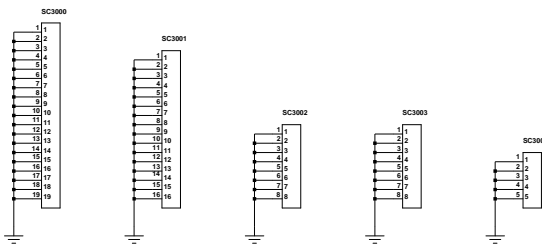
# Connectivity

## BT/WIFI (Broadcom module)

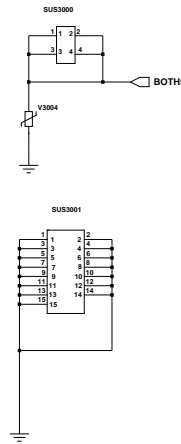
# Conduction



# Design



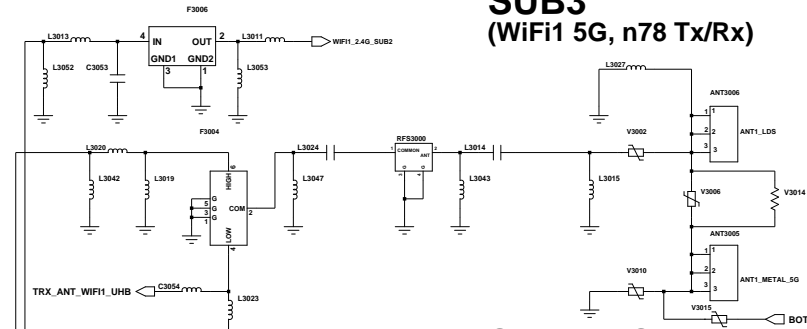
# SHIELDCAN



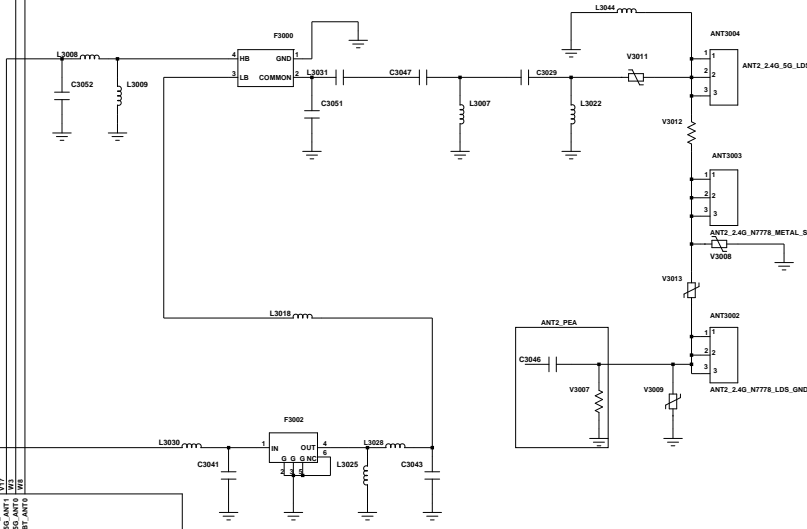
# SUS

### SUB3

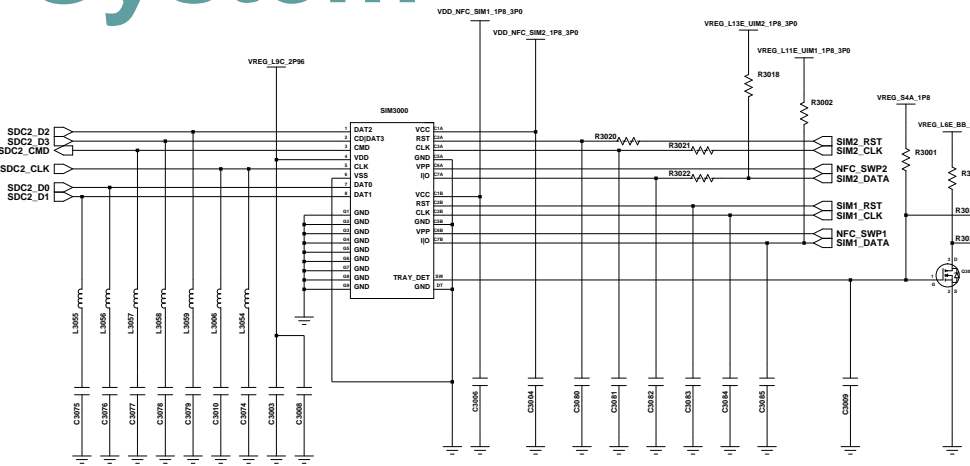
(WiFi1 5G, n78 Tx/Rx)



## SUB4 + SUB7 (WiFi2 2.4G, 5G)

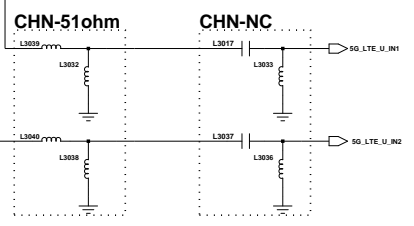
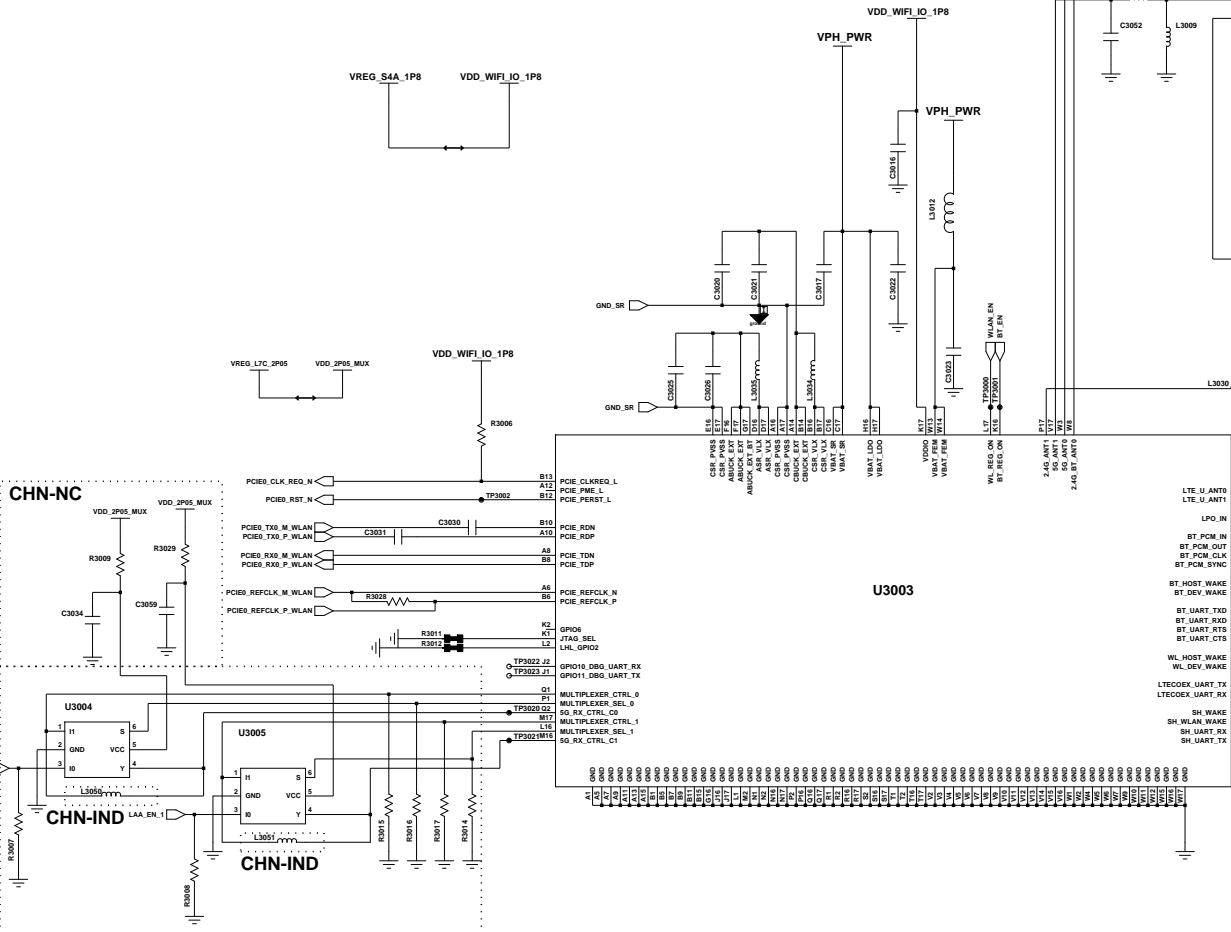


# System

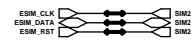


## SIM & SD SOCKET

## e-SIM



Engineer:	SEC			
Drawn by:	SEC			
R&D CHK:		TITLE:		Size:
DOC CTRL CHK:		<b>SM8250 + SDX55M</b>		
MFG ENGR CHK:				
QA CHR:	REV:	Drawing Number:		Page: ?



# Power



# System



# MFC

# SENSORS

# Power



## W/C CONNECTOR

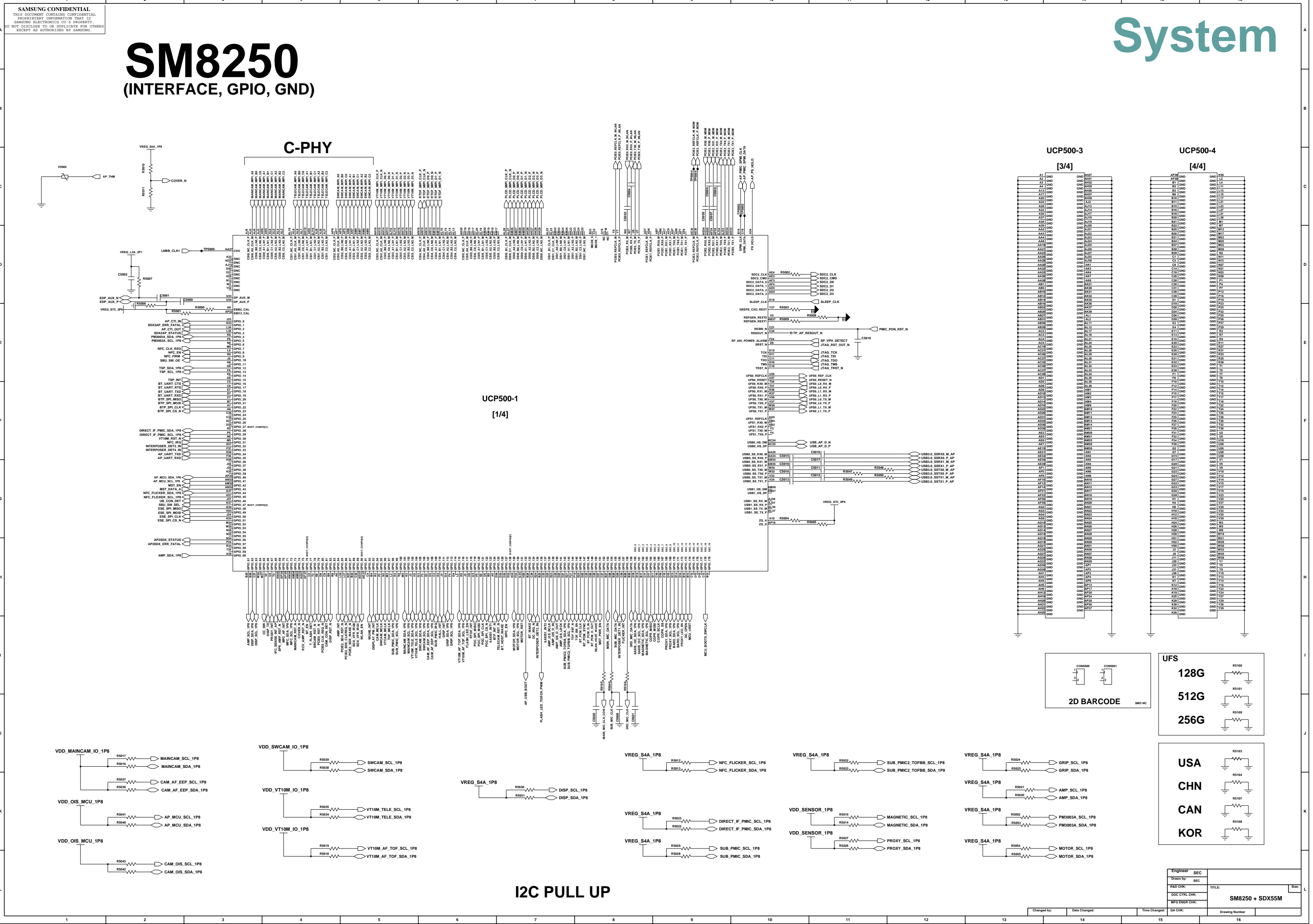
## MST Switch

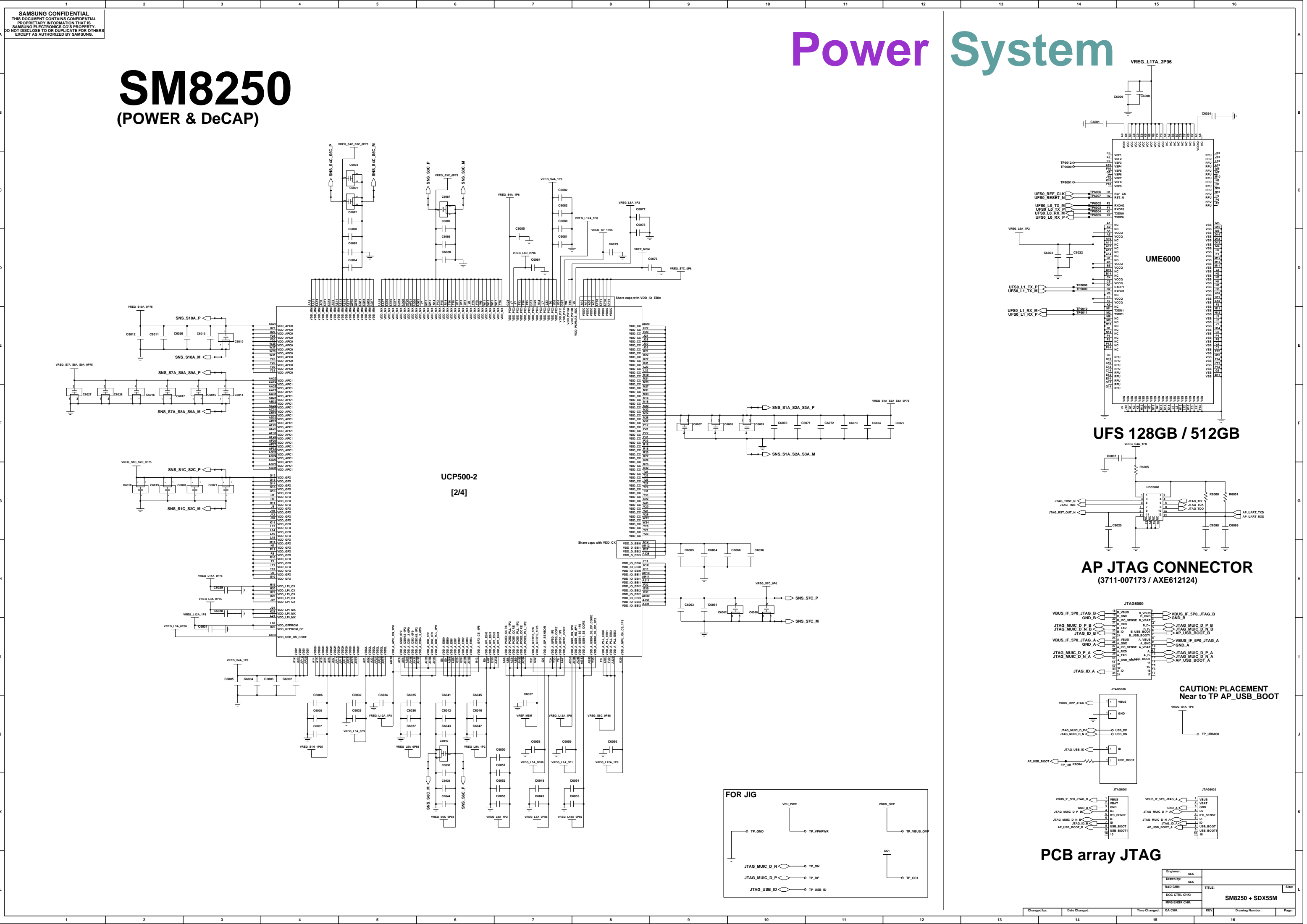
**Barometer SENSOR      6 Axis SENSOR (GYRO,ACCEL)**

# Visual



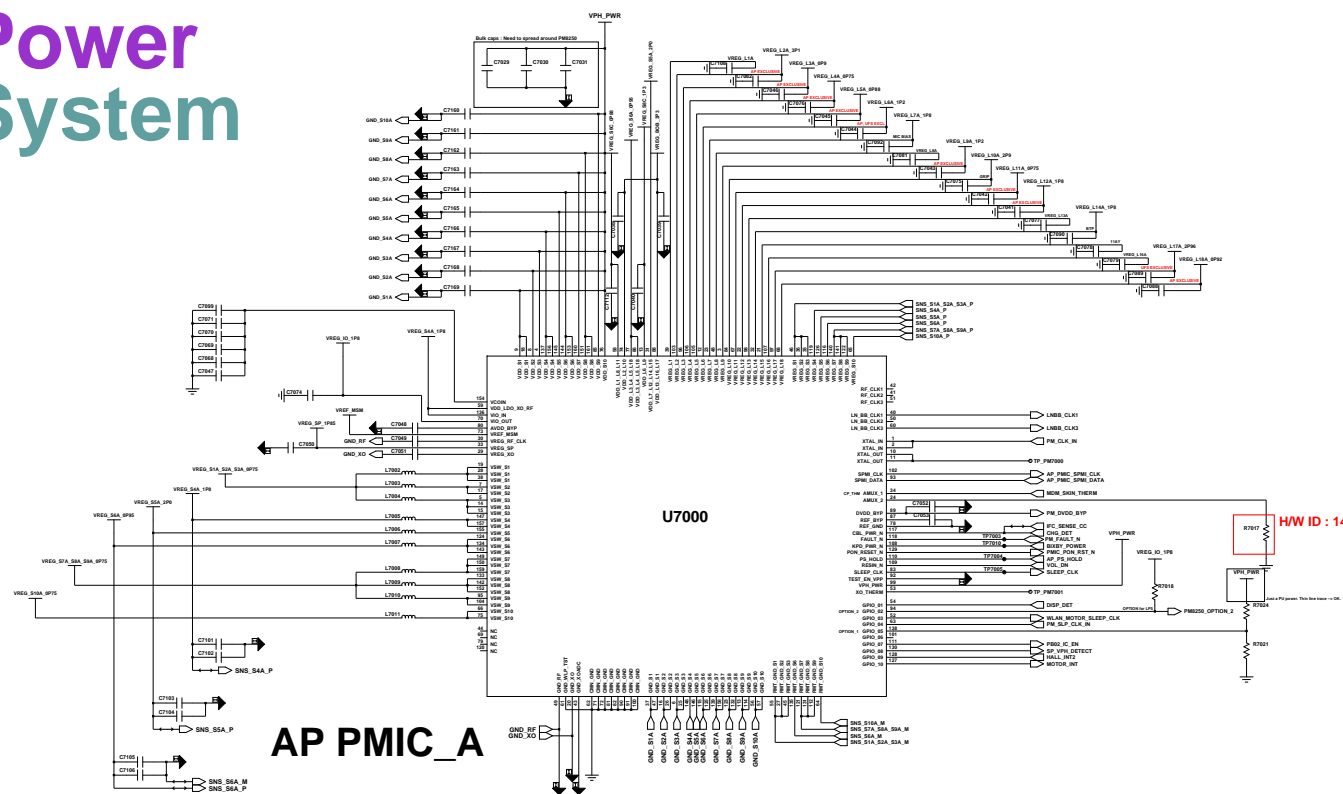
Changed by:	Date Changed:	Time Changed:	QA CHK:	REV	Drawing Number:	Page:
user22	Friday, April 11, 2014	11:27:01 am				4



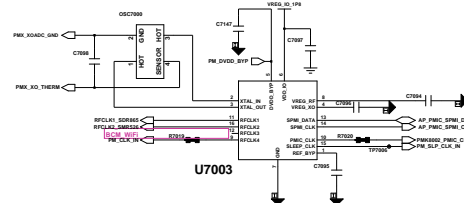




# Power System

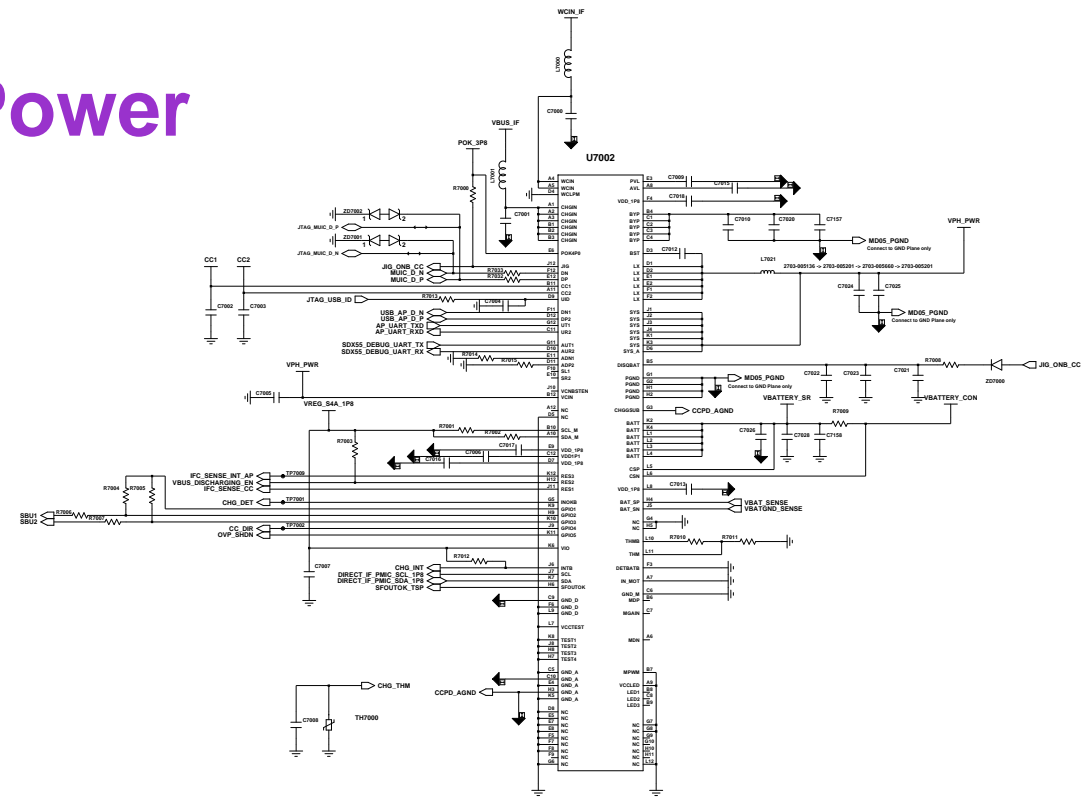


## Clock Generator

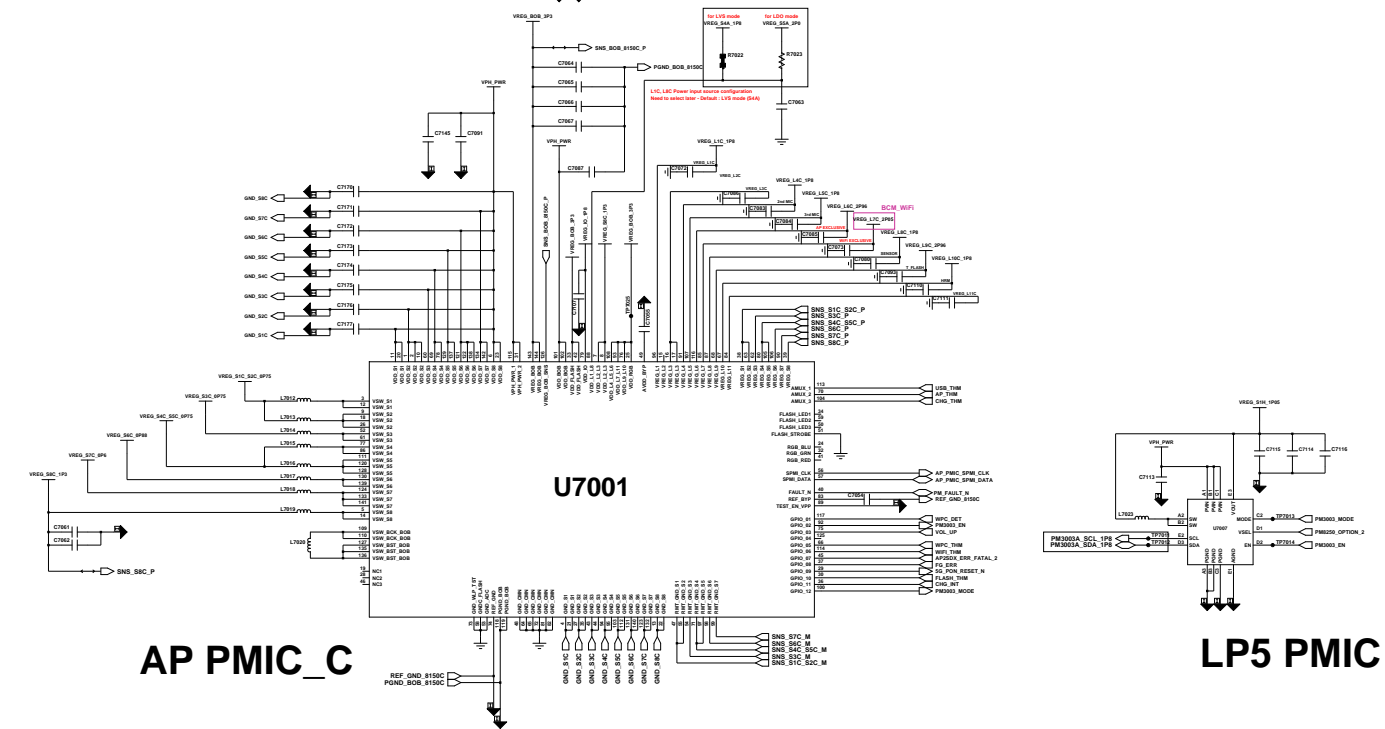


H/W ID table(PM8250 AMUX_2)			
H/W ID	BOARD REVISION	Value	Meas
00	SM8250-SDX55M Rev0.0	6.94K	
01	SM8250-SDX55M Rev0.1	9.1K	
	P2_REV0.0	12.4K	K10
03	P2_REV0.0A	18K	K10
04	P2_REV0.1	22K	K120
05	P2_REV0.1(APIPC V2.0 / TRCV V.3)	30K	
06	SM-G986U_REV0.0(AP V1.0)	39K	K130
07	SM-G986U_REV0.0(AP V2.0)	47K	K130
08	SM-G986U_REV0.1	56K	K140
09	SM-G986U_REV0.2	68K	K150
10	SM-G986D_REV0.3	82K	VY60
11	SM-G986U_REV0.3	100K	VY60
12	SM-G986U_REV0.3A	120K	VY60
13	SM-G986U_REV0.4	150K	VY70
14	SM-G986U_REV0.5/REV0.5A	180K	VY75
15		200K	
16		240K	
17		280K	
18		330K	
19		430K	
20		560K	
21		750K	
22		1000K	
23		1500K	
24		3000K	

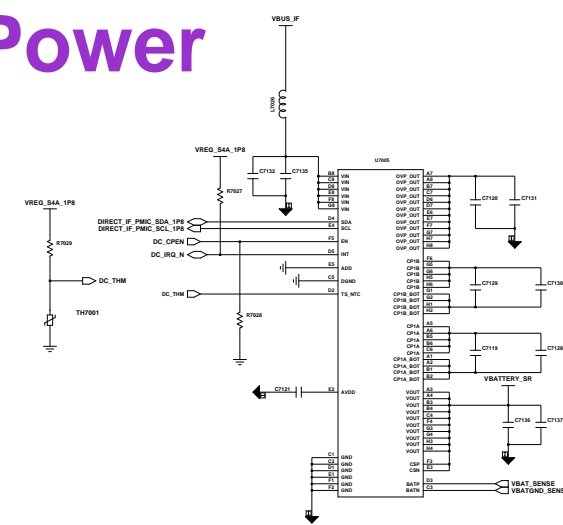
# Power



## IF PMIC (MD05)



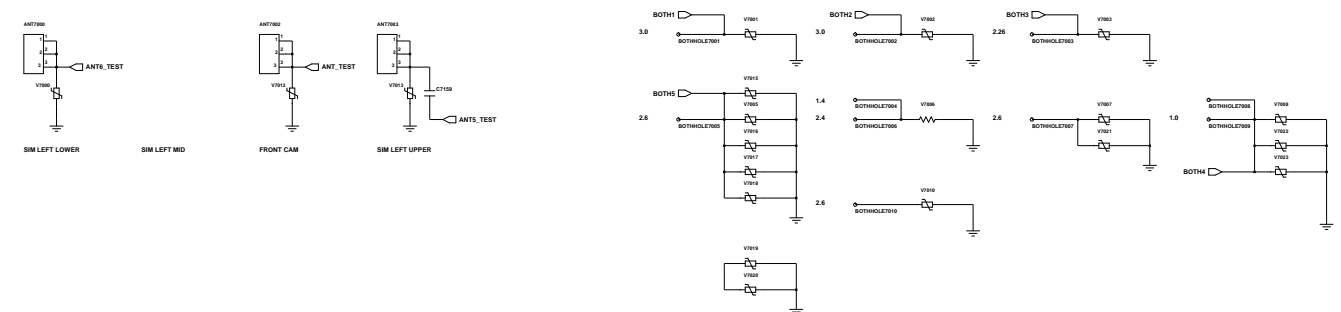
# Power



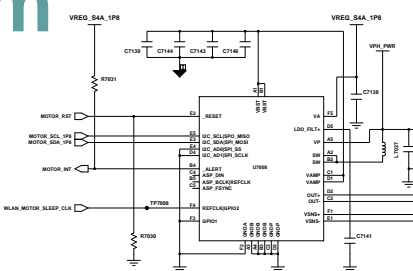
## Direct Charging

## 18W Wireless Charger BQ25910

# SystemRadiation



## Battery Connector



## MOTOR DRV IC

# CCP

## ESD PORON

## BOSS HOLE



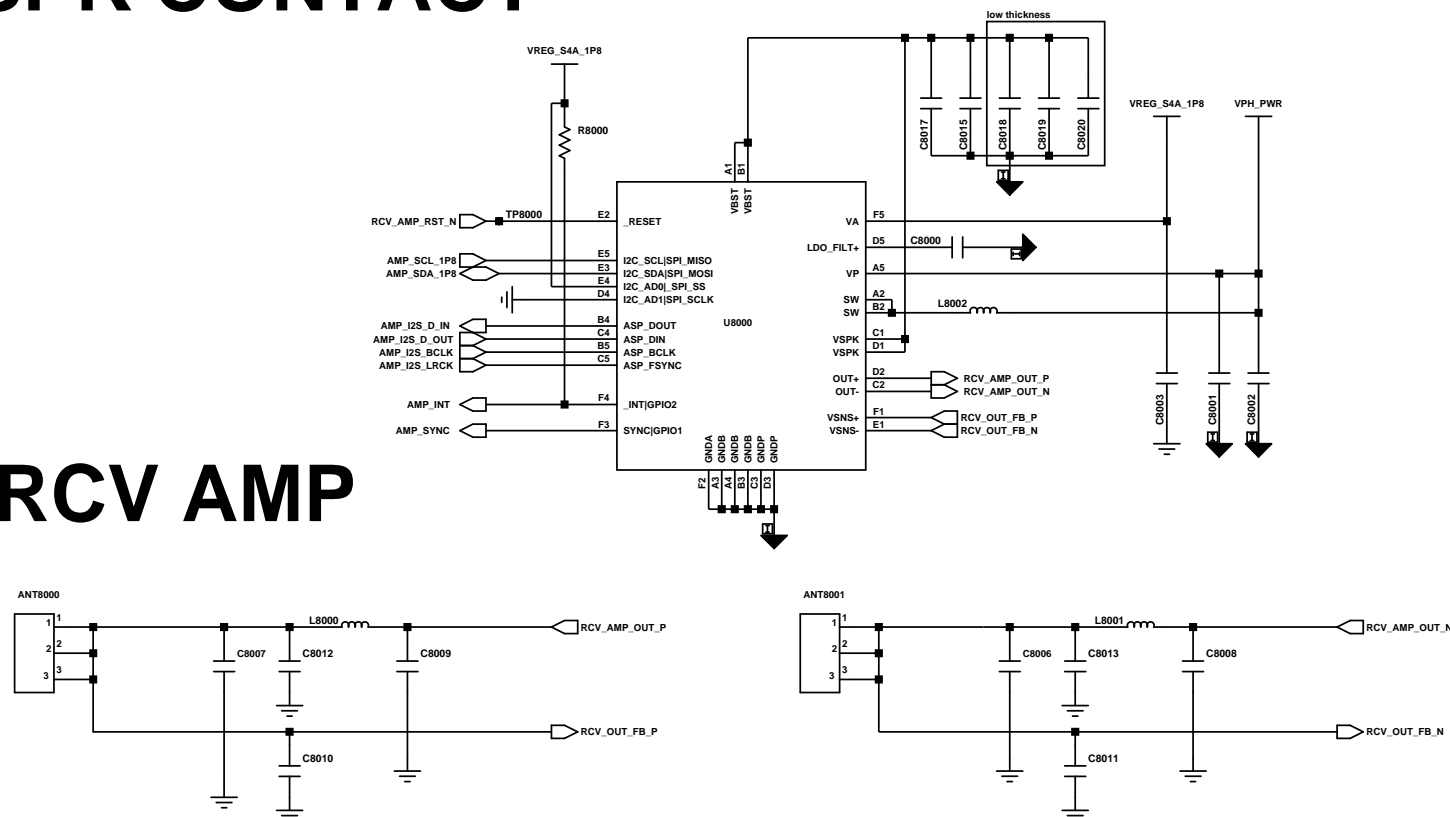
## MAIN MIC

## SPK CONTACT

# RCV AMP

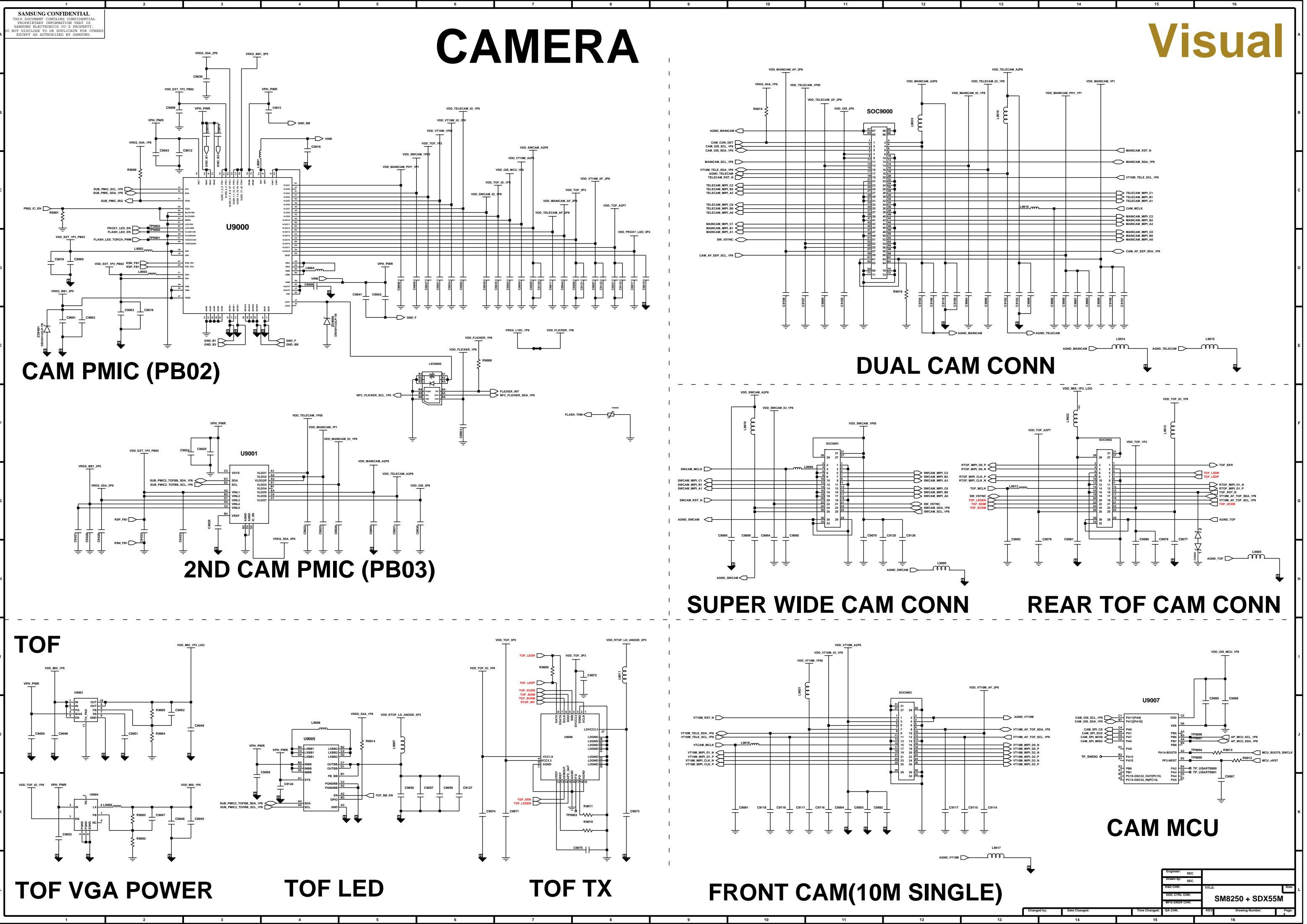
## 2nd MIC

### 3rd MIC



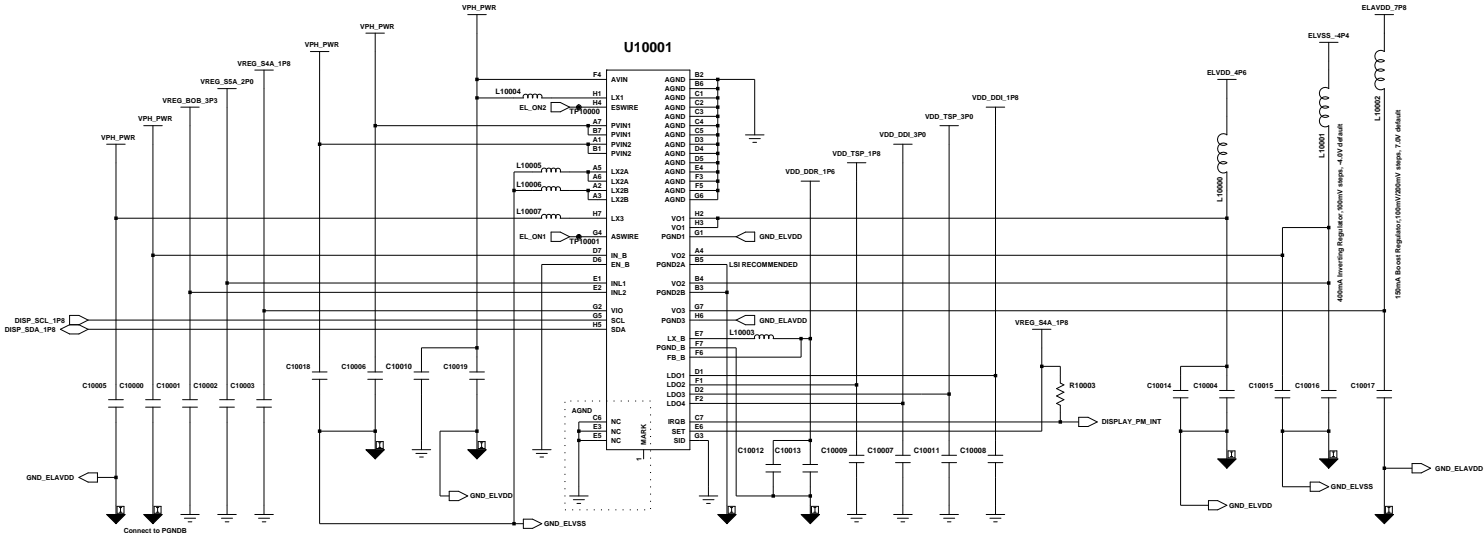
## RCV CONTACT

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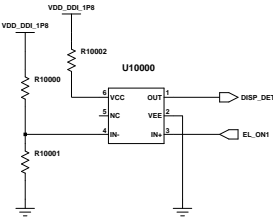


DISPLAY

Visual

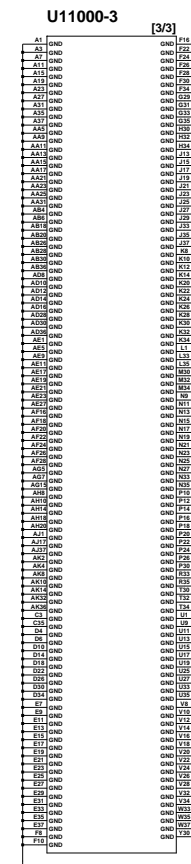


DISPLAY PMIC



DISPLAY CONNECTOR

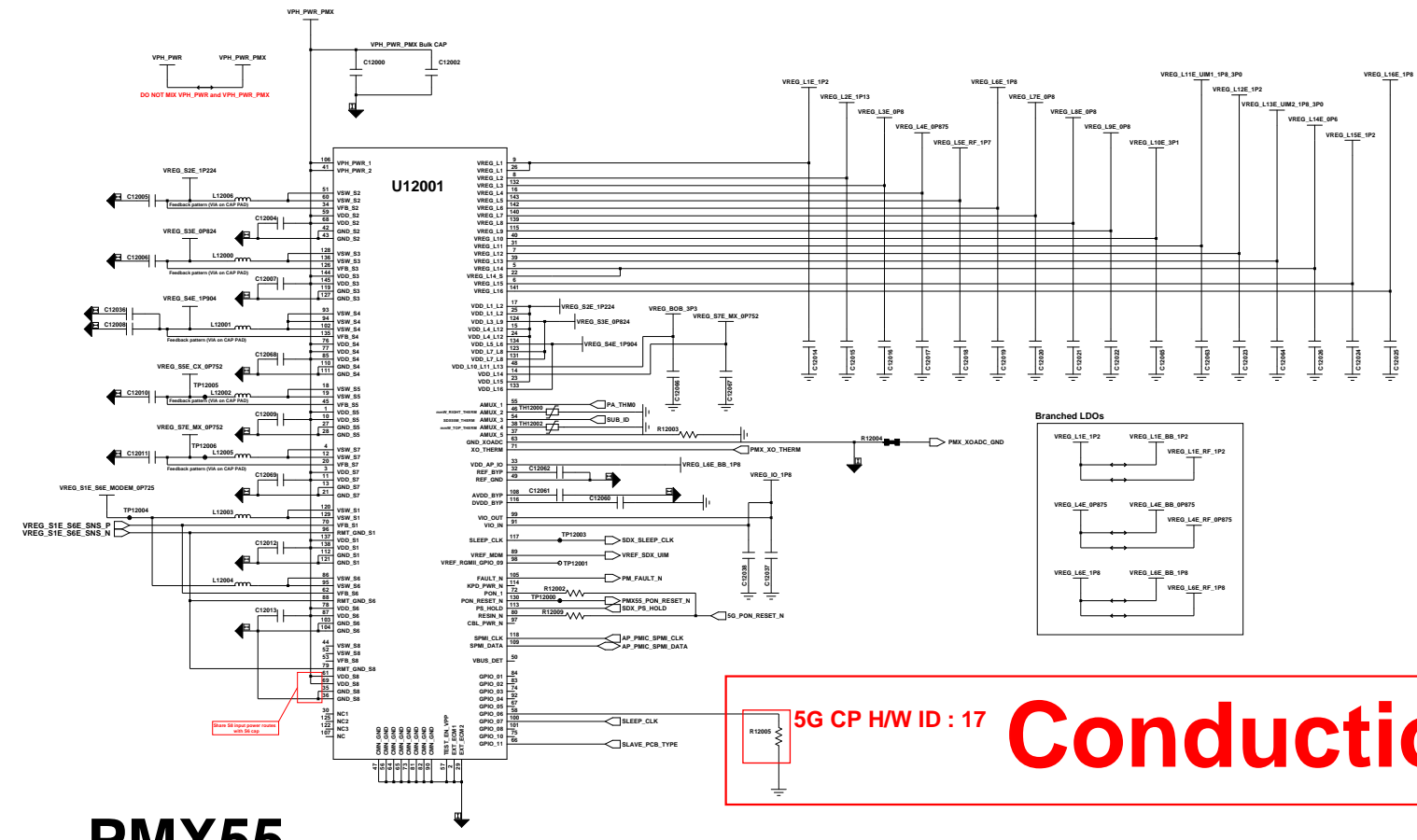
# SDX55M



Engineer: SEC	SAMSUNG ELECTRONICS		
Drawn by: SEC			
R&D CHK:	TITLE:  SM8250 + SDX55M		Size:
DOC CTRL CHK:			
MFG ENGR CHK:			
QA CHK:			
REV:	Drawing Number:		Page:

# CP PMIC

# Power



PMX55

5G CP H/W ID : 17

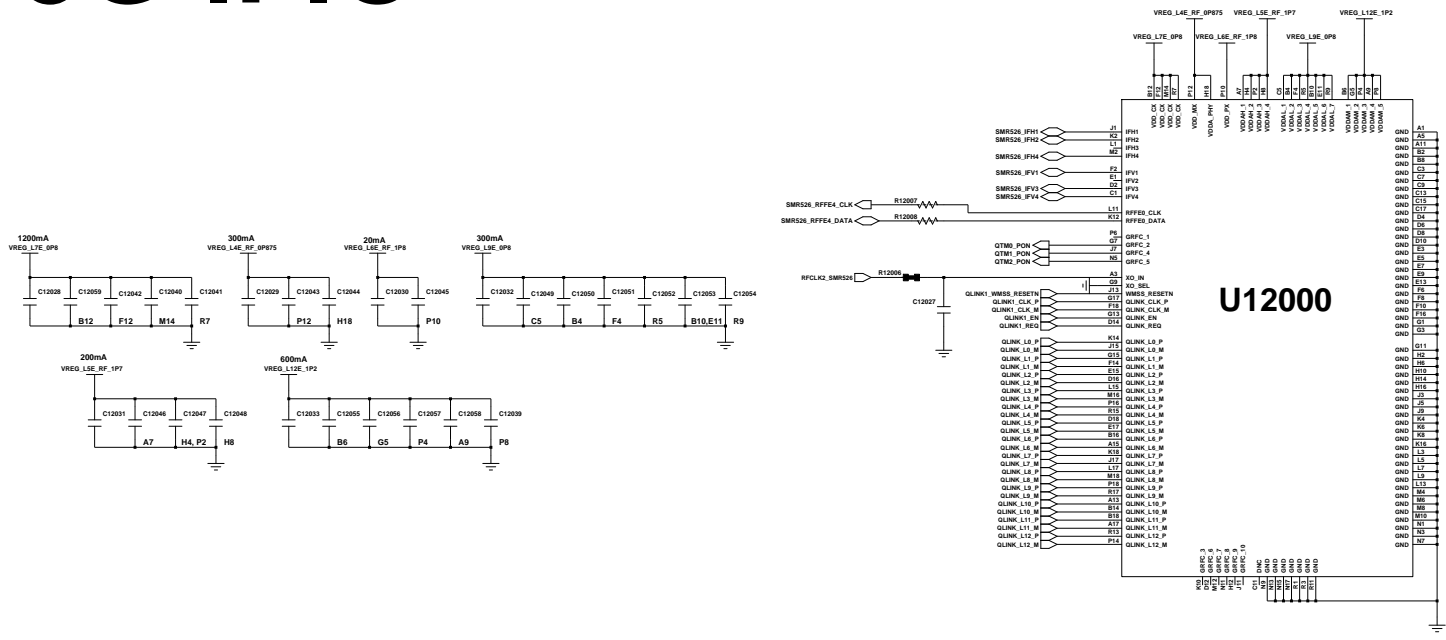
# Conduction

CP H/W ID table (PMX55 GPIO\_06)

HW ID	BOARD REVISION	Value	Mech
00	SM8250+SDX55M Rev0.0	6.04K	
01		9.1K	
02	P2_REV0.0	12.4K	KI10
03	P2_REV0.0A	18K	KI10
04	P2_REV0.1	22K	KI20
05	P2_REV0.1(AP/CP V2.0 / TRCV V3.0)	30K	
06	SM-G986U_REV0.0(AP V1.0)	39K	KI30
07	SM-G986U_REV0.0(AP V1.0)	47K	KI30
08	SM-G986U_REV0.1	56K	KI40
09	SM-G986U_REV0.1 (QPM6585 NC)	68K	KI40
10	SM-G986U_REV0.1 (QPM6585,8972 NC)	82K	KI40
11	SM-G986U_REV0.2	100K	KI50
12	SM-G986U_REV0.3	120K	VY60
13	SM-G986U_REV0.3A	150K	VY60
14	SM-G986U_REV0.4	180K	VY70
15	SM-G986U_REV0.4 (QAT5515)	200K	VY70
16	SM-G986U_REV0.5	240K	VY75
17	SM-G986U_REV0.5A	280K	VY75
18		330K	
19		430K	
20		560K	
21		750K	
22		1000K	
23		1500K	
24		3000K	

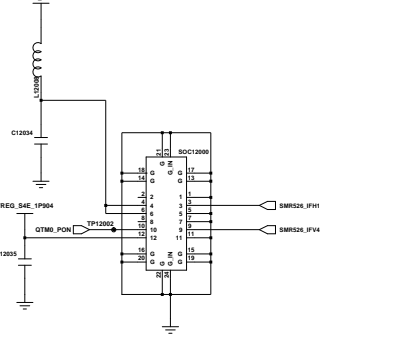
# 5G IFIC

# Radiation



mmW\_ANT\_CONN (Left)

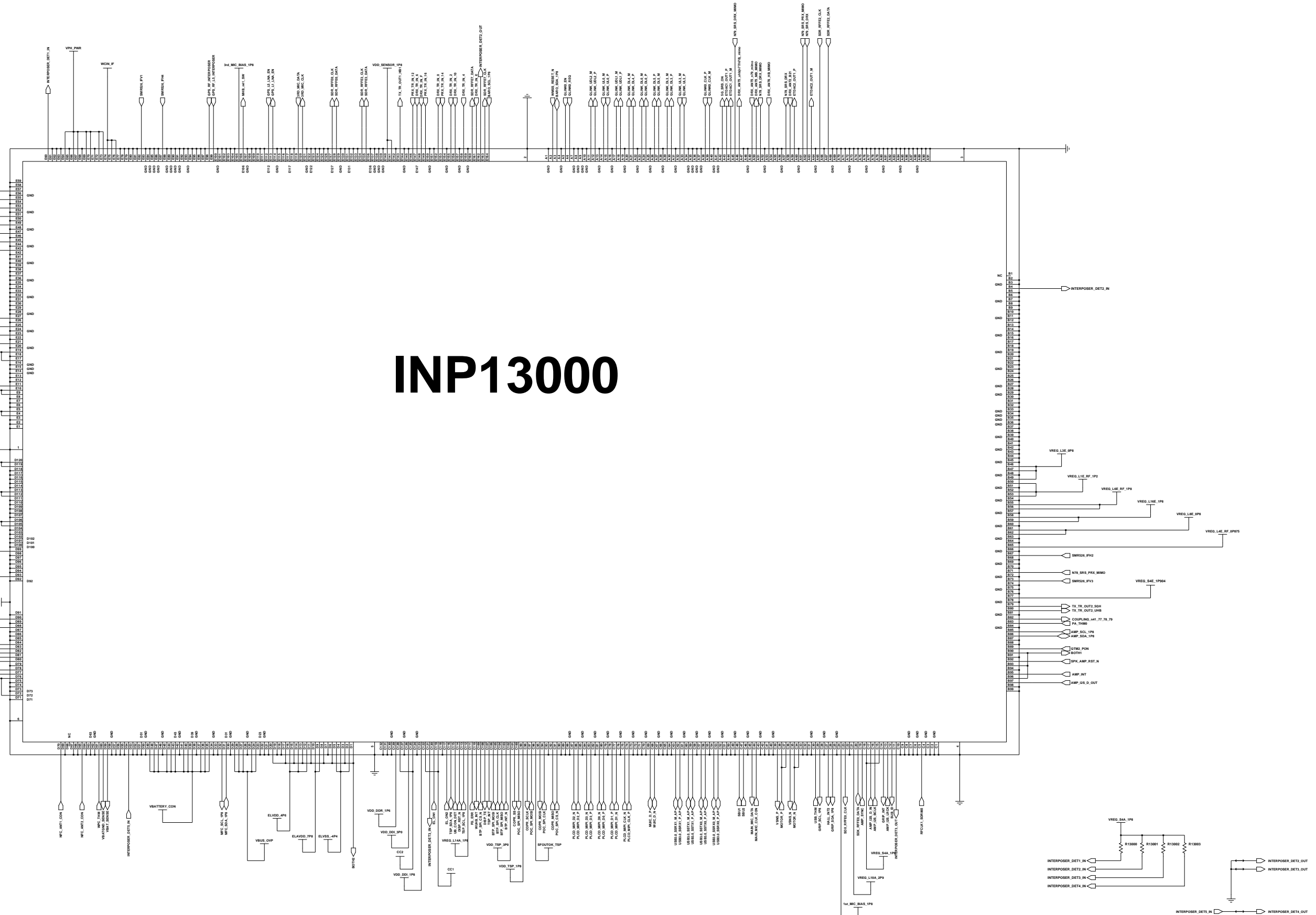
mmW\_ANT\_CONN (Right)



mmW\_ANT\_CONN (Up)

Engineer:	SEC	SAMSUNG ELECTRONICS	
Drawn by:	SEC		
R&D CHK:		TITLE:	Size:
DOC CTRL CHK:		SM8250 + SDX55M	
MFG ENGR CHK:			
Changed by:	Date Changed:	Time Changed:	QA CHK:
oaf	Thursday, December 1, 2016	3:17:21 pm	
Drawing Number:		Page:	
		13	

# INTERPOSER



Engineer:	SEC	SAMSUNG ELECTRONICS		
Drawn by:	SEC			
R&D CHK:		TITLE:		Size:
DOC CTRL CHK:		SM8250 + SDX55M		
MFG ENGR CHK:				
d: QA CHK:		REV:	Drawing Number:	Page:



1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	
<div>SAMSUNG CONFIDENTIAL THIS DOCUMENT CONTAINS CONFIDENTIAL PROPRIETARY INFORMATION THAT IS SAMSUNG ELECTRONICS CO.'S PROPERTY. DO NOT DISCLOSE TO OR DUPLICATE FOR OTHERS EXCEPT AS AUTHORIZED BY SAMSUNG.</div>																A
																B
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																H
																I
																J
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																L
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	

# HUBBLE 2 NA SLAVE REV0.5A

SM-G986U Common

2019. 11.27

made 1203 , SMD 1209

- sheet01 : RF (1/2), MMW Conn
- sheet02 : RF (2/2), TRCV\_SDR865
- sheet03 : BT/WIFI, SIM, SHILDCAN
- sheet04 : MFC, MFC Conn, 6XIS, BATT Conn, SPK AMP
- sheet05 : Lower SUB Conn, KEYLESS, DISPLAY Con
- sheet06 : INTERPOSER

Engineer:			
Drawn by:			
RDG CHK:	TITLE:		Size:
DOC CTRL CHK:			
MFG ENGR CHK:			

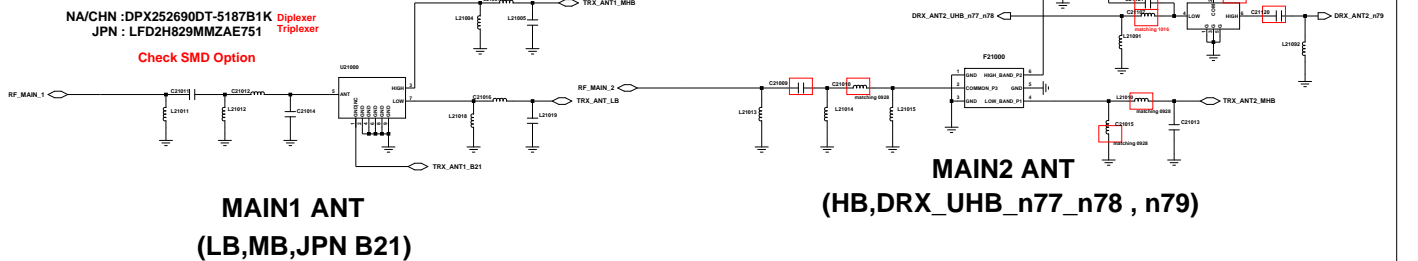
# Conduction

## SMD option

NA : C2112, C2121 : 100pF, F21005 OPEN  
CHN/JPN : C2112, C2121 : OPEN, F21005 LFD213G75PAEF228  
N79 NA not support, CHN/JPN support

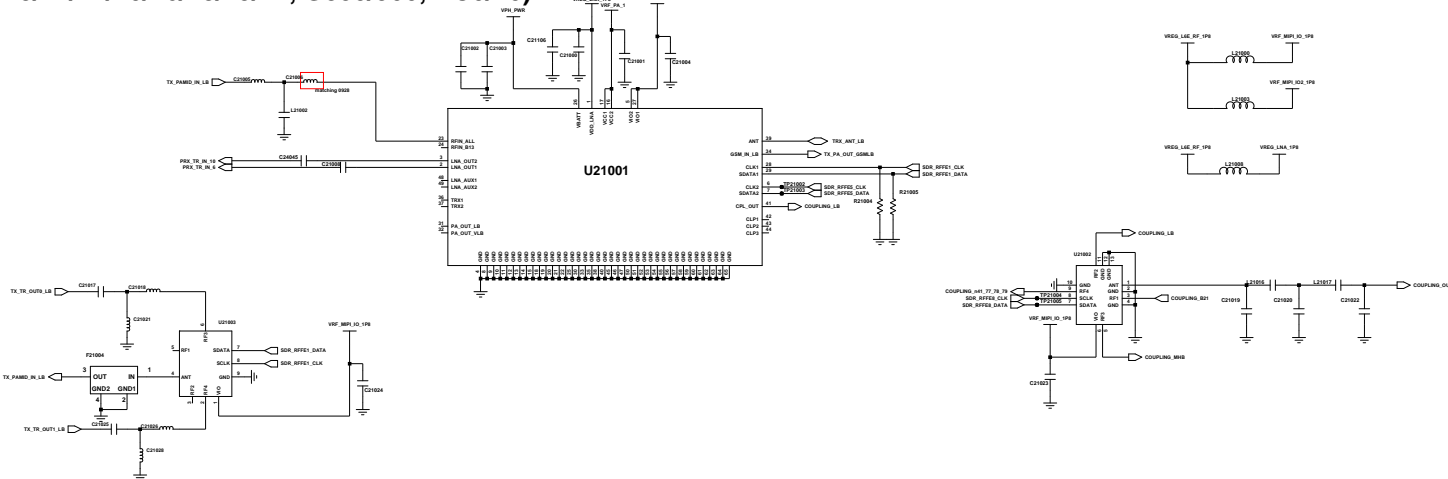
## NA DELETE

NA : C21120, L21092 : OPEN  
CHN/JPN : C21120, L21092 : matching value



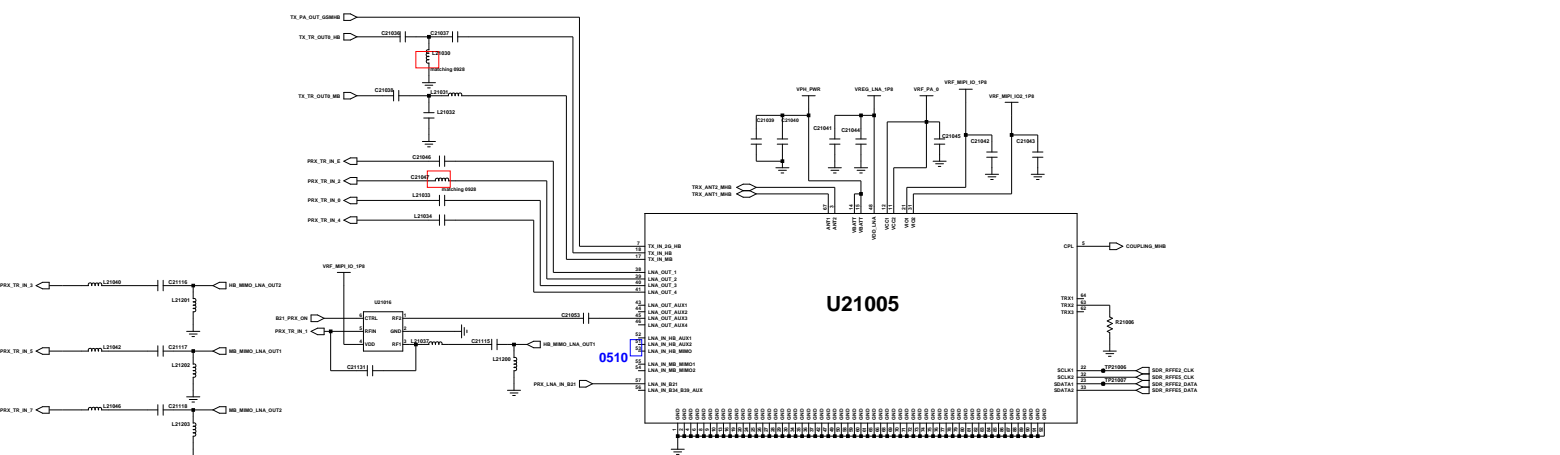
## LB LPAMID

(B5/8/12/13/14/17/20/26/28/29/71, G850/900, BC0/10)



## OMH LPAMID

(B1/2/3/4/7/25/30/34/38/39/40/41/66, G1800/1900, BC1)

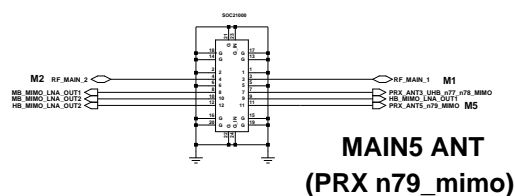


## MAIN3 ANT

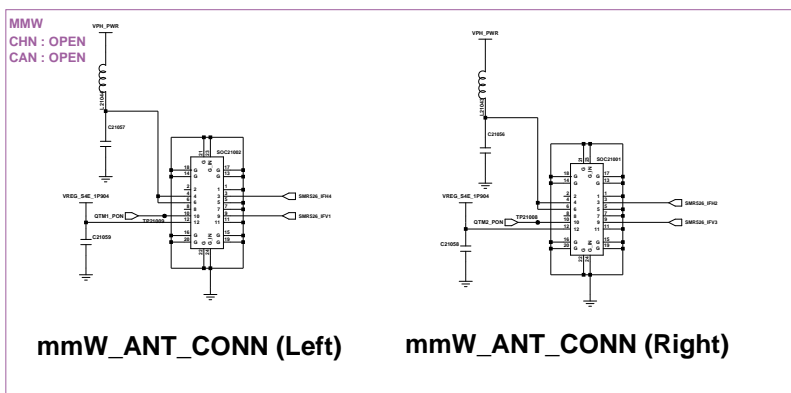
( PRX hb MIMO , PRX uhb/n77/n78 mimo )

## MAIN4 ANT

( PRX mb MIMO )

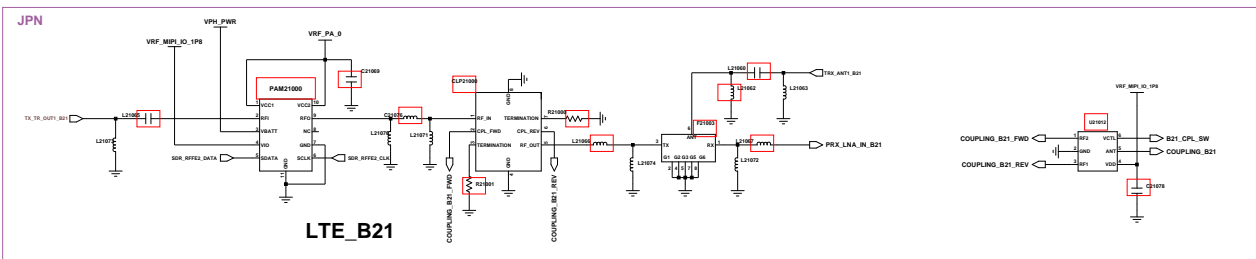


## FRC connector



## SMD option ( B21 )

NA / CHN no support  
JPN support

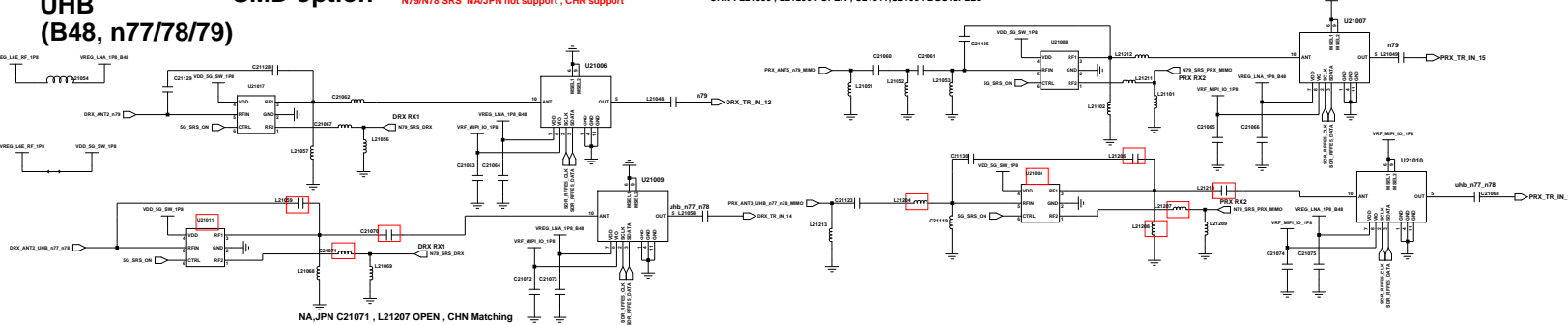


## UHB (B48, n77/78/79)

## SMD option

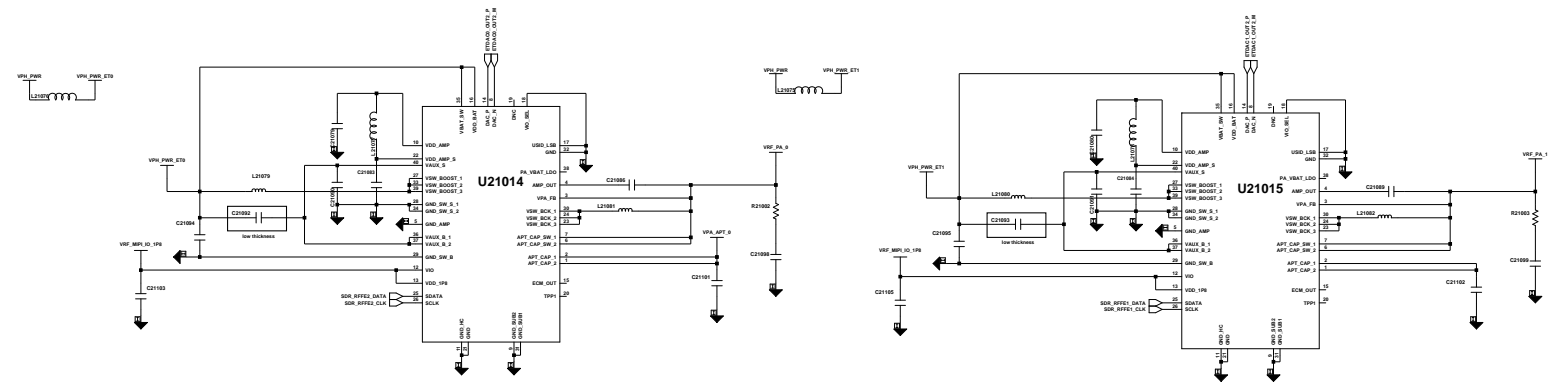
N79 NA not support, CHN/JPN support  
N79/N78 SRS NA/JPN not support, CHN support

NA, JPN : L21059, L21206 : 100pF, U21011, U21004 OPEN  
CHN : L21059, L21206 : OPEN, U21011, U21004 BGS12P2L6

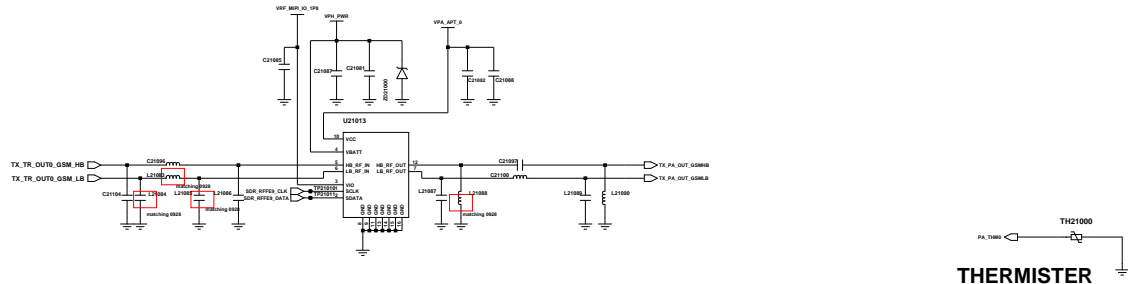


## ET Modulator(QET5100#0)

## ET Modulator(QET5100#1)

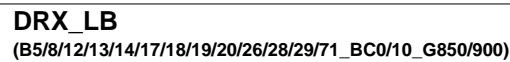


## 2G\_PA





# GPS\_L1 Connectivity



# Conduction

**DRX\_MHB\_1**  
(B1/2/3/4/7/25/30/39/41/66\_BC1\_DCS/PCS)



**DRX\_MHB\_2**  
(B2/4/7/25/30/41/66)



JPN : C22107 100pF , U22006 OPEN  
CHN : C22107 OPEN , U22006 BGS12P2L6

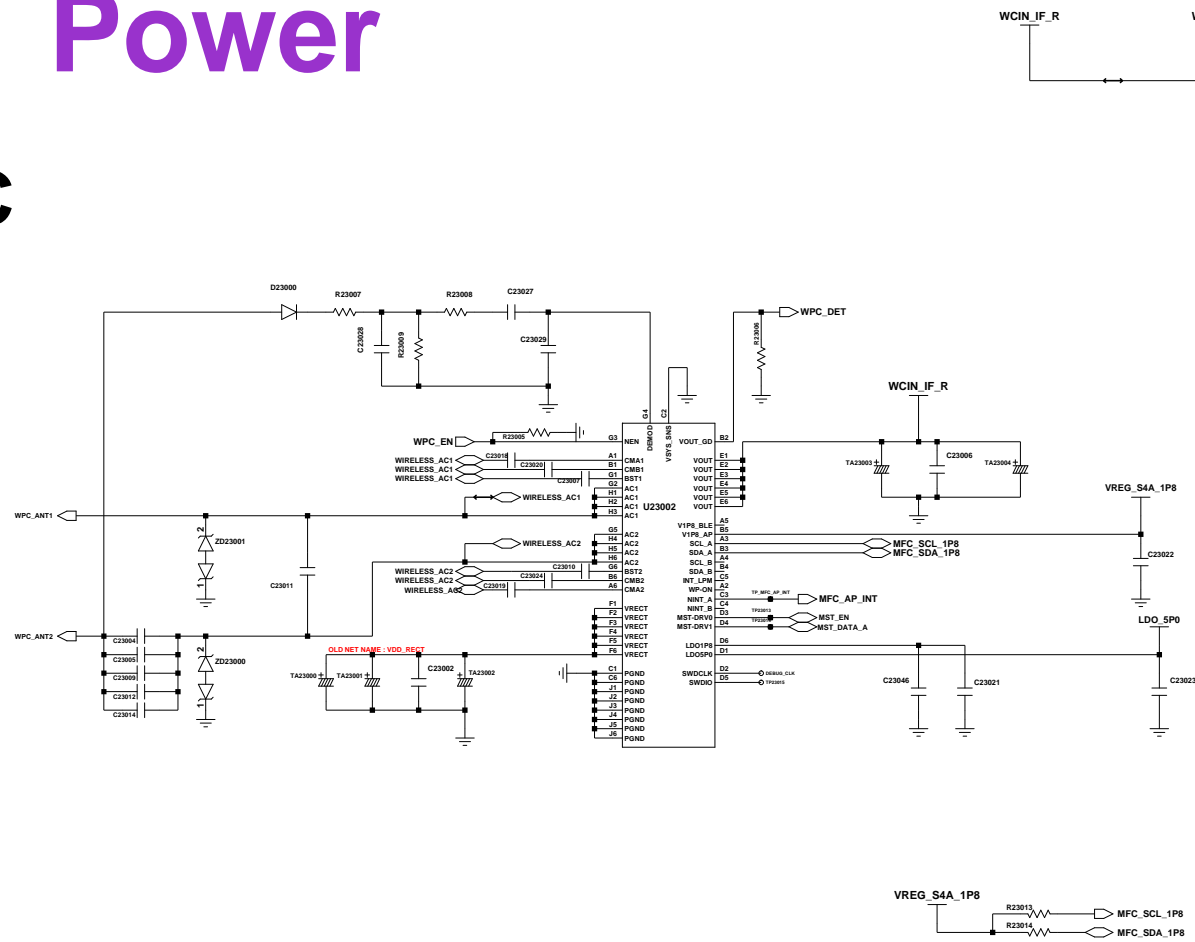


NA/ JPN : C22100 100pF , U22001 OPEN  
CHN : C2100 OPEN , U22001 BGS12P2L6

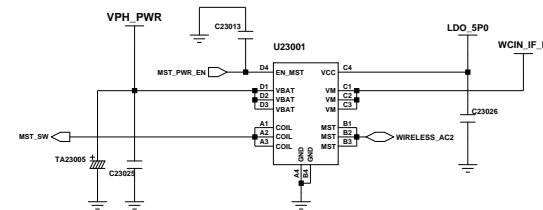
**SRS - 1T4R**  
(n77/78)



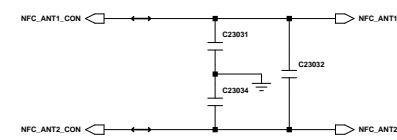
# MFC



## MST Switch

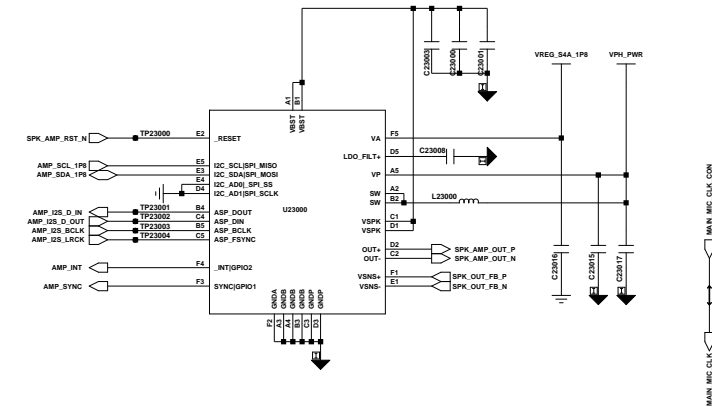


# NFC

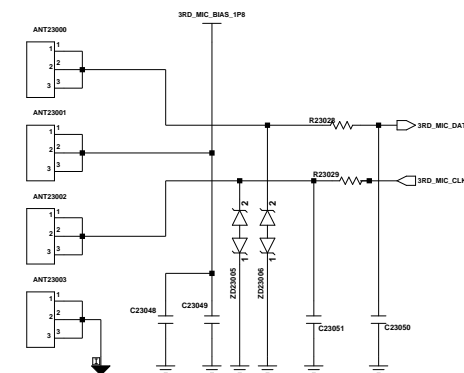


# SPK AMP

# AUDIO



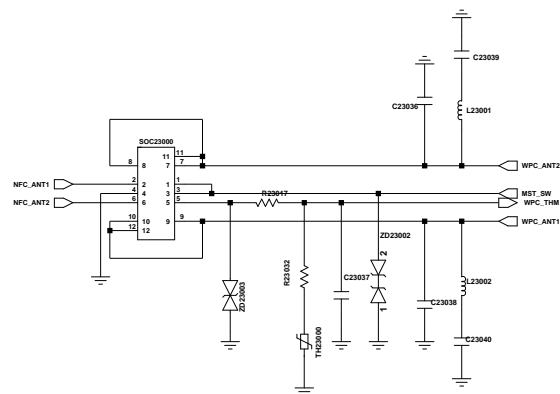
### 3rd MIC



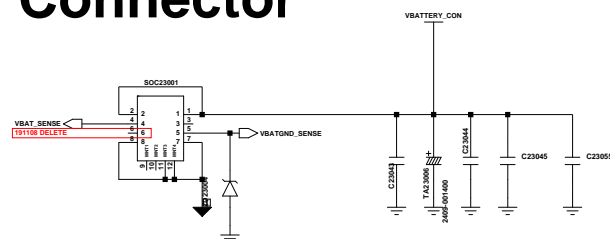
# Visual



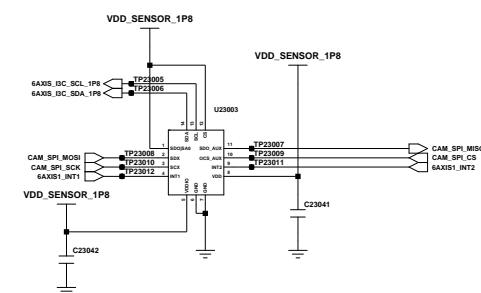
## W/C CONNECTOR



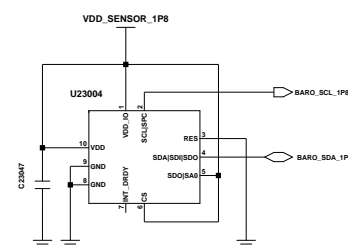
## Battery Connector



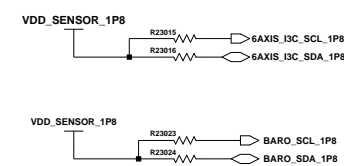
# Power



# SENSORS

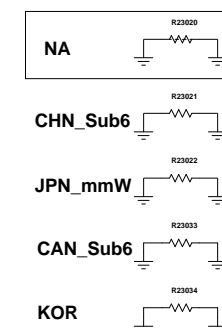
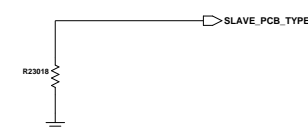


## 6 Axis SENSOR (GYRO,ACCEL)



# System

SLAVE_TYPE	
	ADC
NA_Sub6_mmW(G986U)	68K
NA_CAN_Sub6(G986W)	100K
CHN_Sub6(G9860)	150K
LA_LTE	200K
KOR_Sub6(G956N)	270K
MEA_LTE	430K
JPN_mmW(G986D)	750K
JPN_LTE	1500K
For JIG	OPEN



Engineer:	SEC			
Drawn by:	SEC			
R&D CHK:		TITLE:		Size
DQC CTRL CHK:		<b>SM8250 + SDX55M</b>		16 x 12
MFG ENGR CHK:				
ged: QA CHK:	REV:	Drawing Number:		Page:





Engineer: SEC	SAMSUNG ELECTRONICS		
Drawn by: SEC			
R&D CHK:	TITLE:  SM8250 + SDX55M		Size:
DOC CTRL CHK:			
MFG ENGR CHK:			
QA CHK:			
REV:	Drawing Number:		Page:

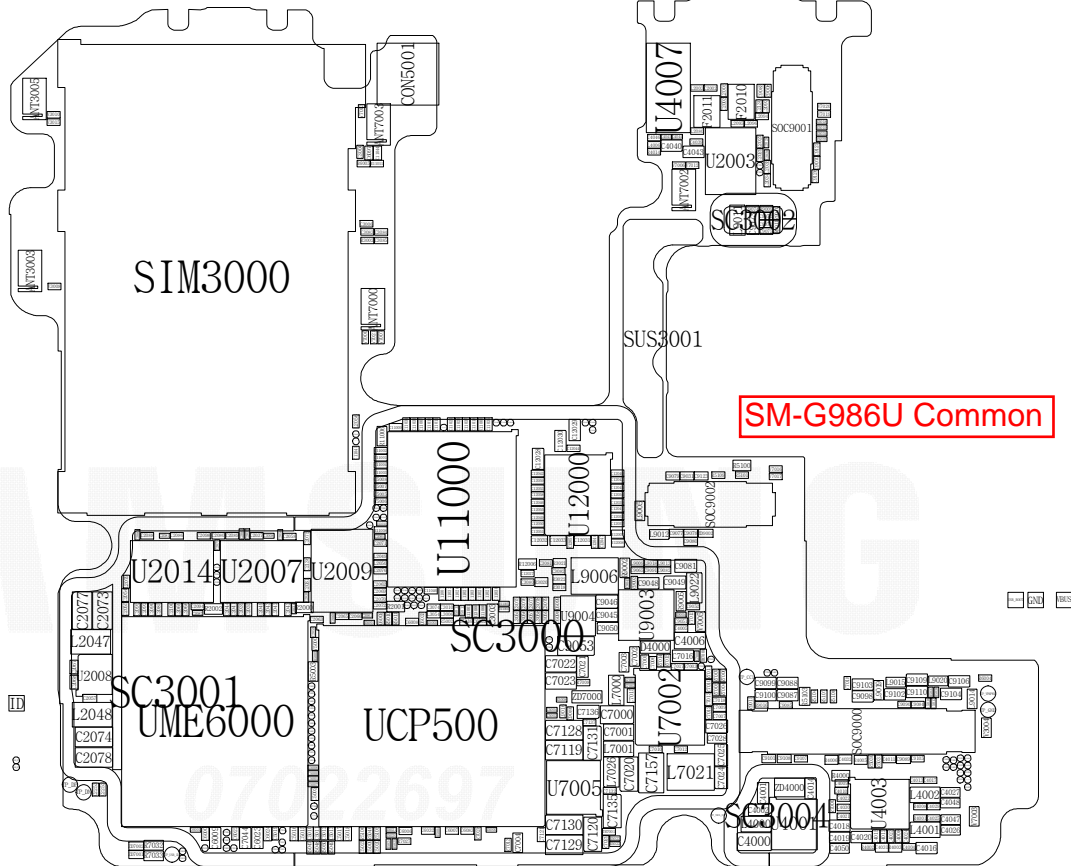


SM-G986U Common

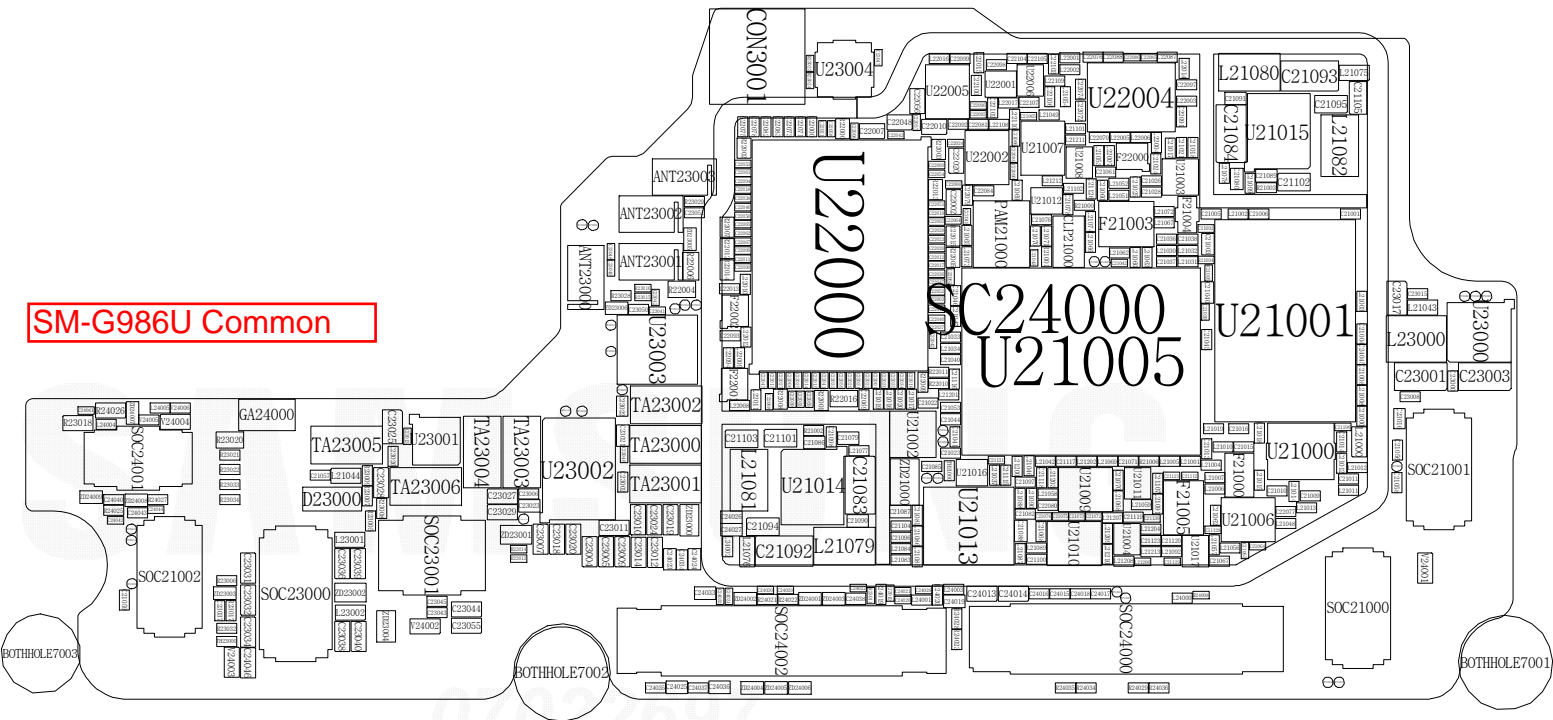
JTAG6000

JTAG6002

JTAG6001



SM-G986U Common



1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
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I															
J															
K															
L															
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16

# SM-G986W MASTER REV0.5A

- sheet01 : RF (1/2)
- sheet02 : RF (2/2)
- sheet03 : BT/WIFI, SIM, SHILDCAN
- sheet04 : NFC, MFC, OVP LS, SENSORS
- sheet05 : AP\_SM8250
- sheet06 : AP\_SM8250 POWER/GND, JTAG, UFS
- sheet07 : PM8250, IF PMIC(CC IC), D/C
- sheet08 : AUDIO
- sheet09 : CAMERA
- sheet10 : DISPLAY
- sheet11 : CP\_SDX55M
- sheet12 : CP PMIC, 5G IFIC, 5G Conn
- sheet13 : INTERPOSER

2019. 11. 28

1216 OPEN -> NC

0213 R12005 Change

Engineer:			
Drawn by:			
RDG CHK:	TITLE:		Size:
DOC CTRL CHK:			
MFG ENGR CHK:			
QA CHK:	REV:	Drawing Number:	Page:

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MAIN ANT

MAIN1-1 ANT

MAIN1-2 ANT

MAIN4 ANT

MAIN2 ANT

M1-1

M4

M1-2

M2

M3

MAIN3 ANT

FRC connector

JPN

LTE\_B21

2G\_PA

THERMISTER

LB LPAMID  
(B5/8/12/13/14/17/20/26/28/29/71, G850/900, BC0/10)

OMH LPAMID  
(B1/2/3/4/7/25/30/34/38/39/40/41/66, G1800/1900, BC1)

UHB  
(B48, n77/78/79)

ET Modulator(QET5100#0)

ET Modulator(QET5100#1)



Engineer:	SEC	TITLE: SM8250 + SDX55M		Sheet
Drawn by:	SEC			
E&D Check:				
QA/QC Check:				
QA Check:		REV:	Drawing Number:	





# Connectivity

BT/WIFI  
(Broadcom module)

# Conduction

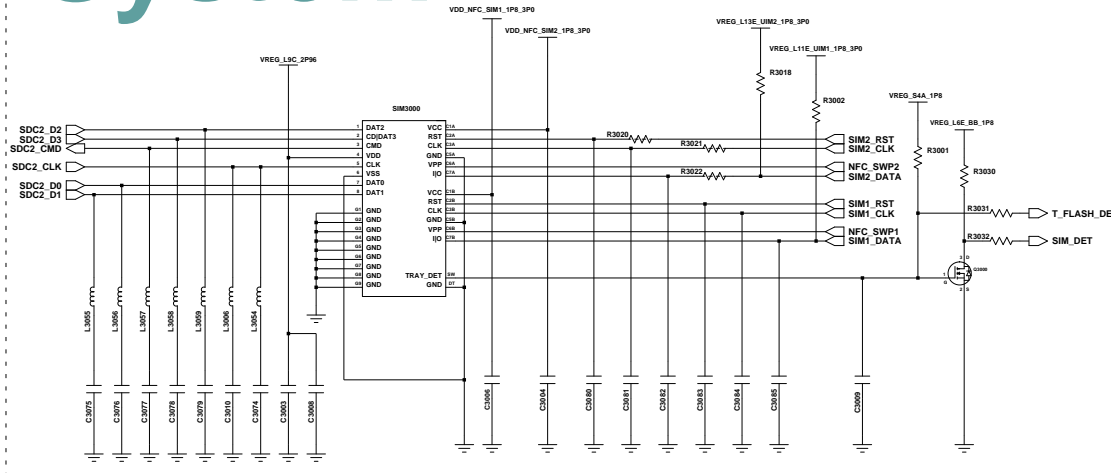
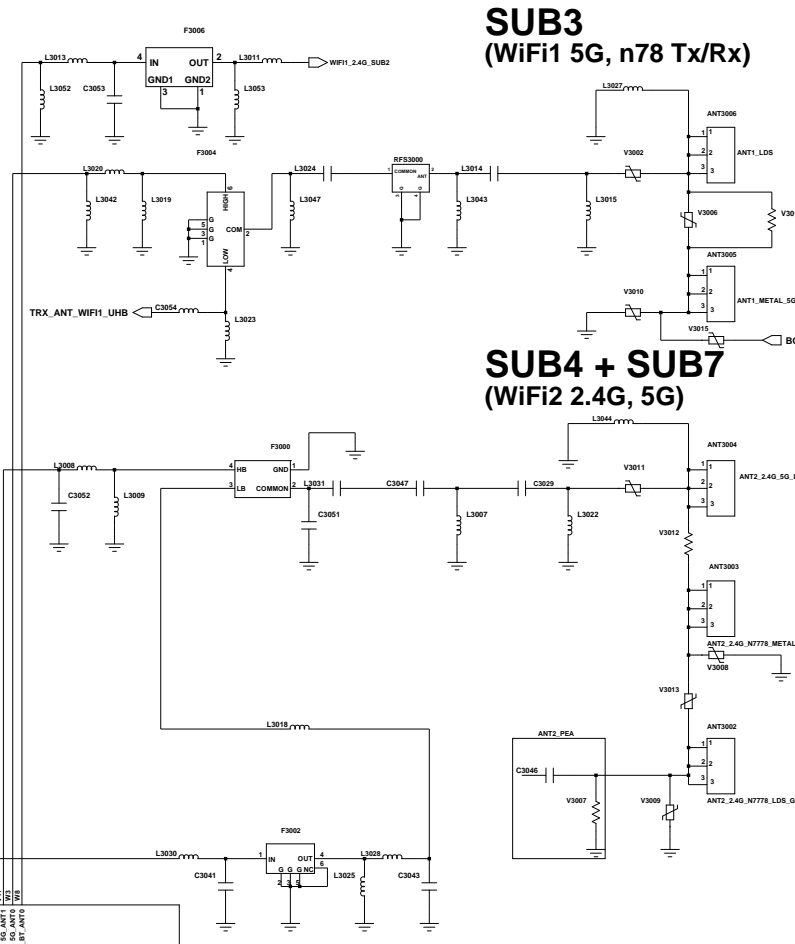
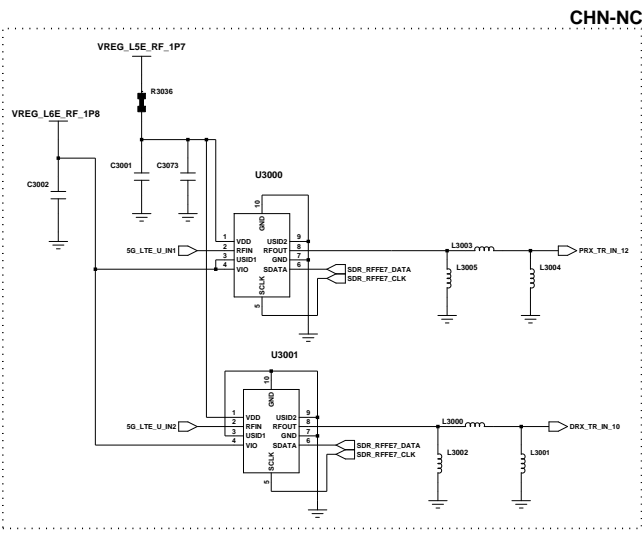
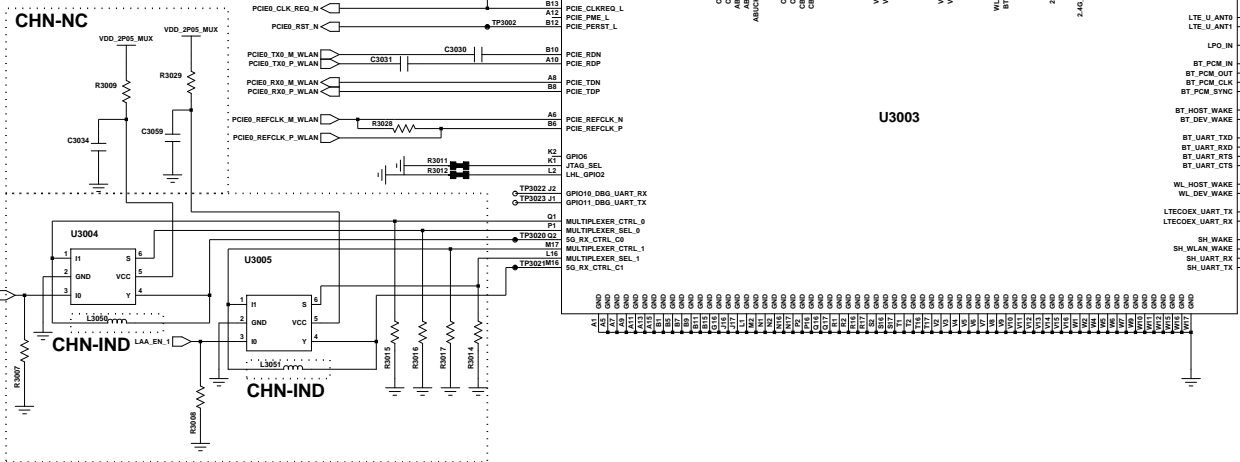
# Design

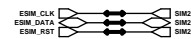
SUS

# System

SIM & SD SOCKET

e-SIM





# Power



# System



# MFC

# SENSORS

# Power

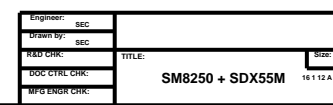


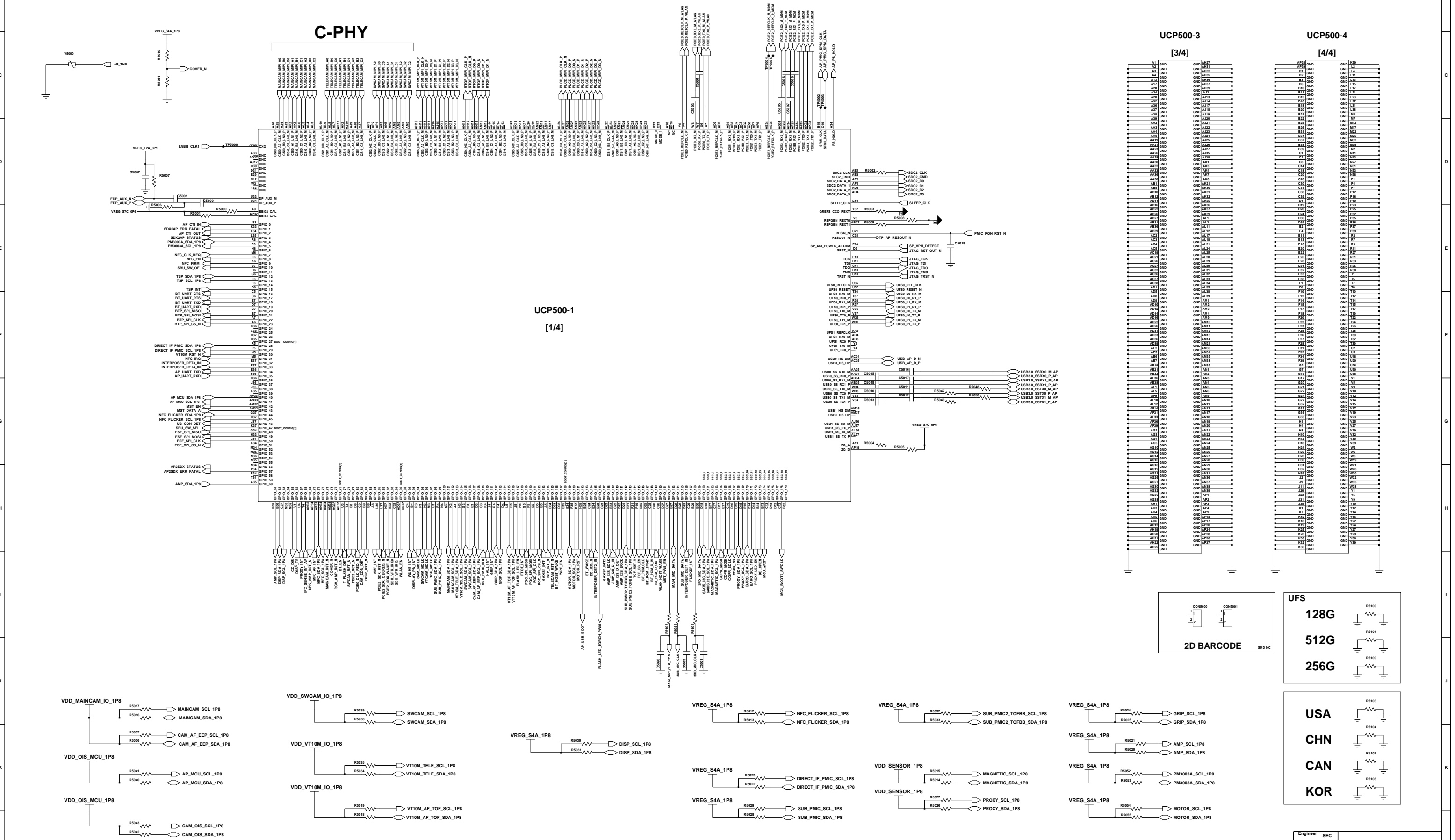
## W/C CONNECTOR

## MST Switch

**Barometer SENSOR      6 Axis SENSOR (GYRO,ACCEL)**

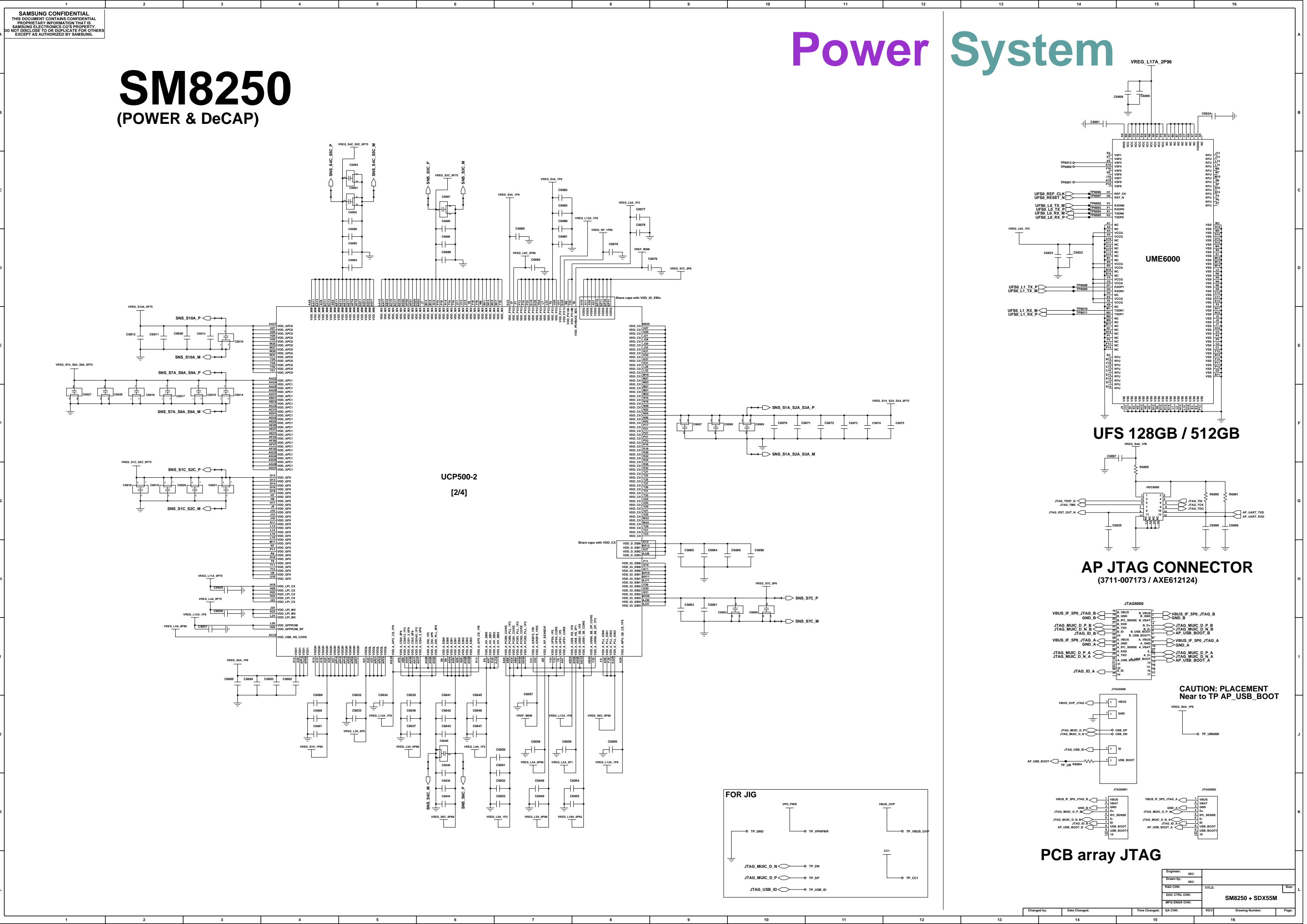
# Visual



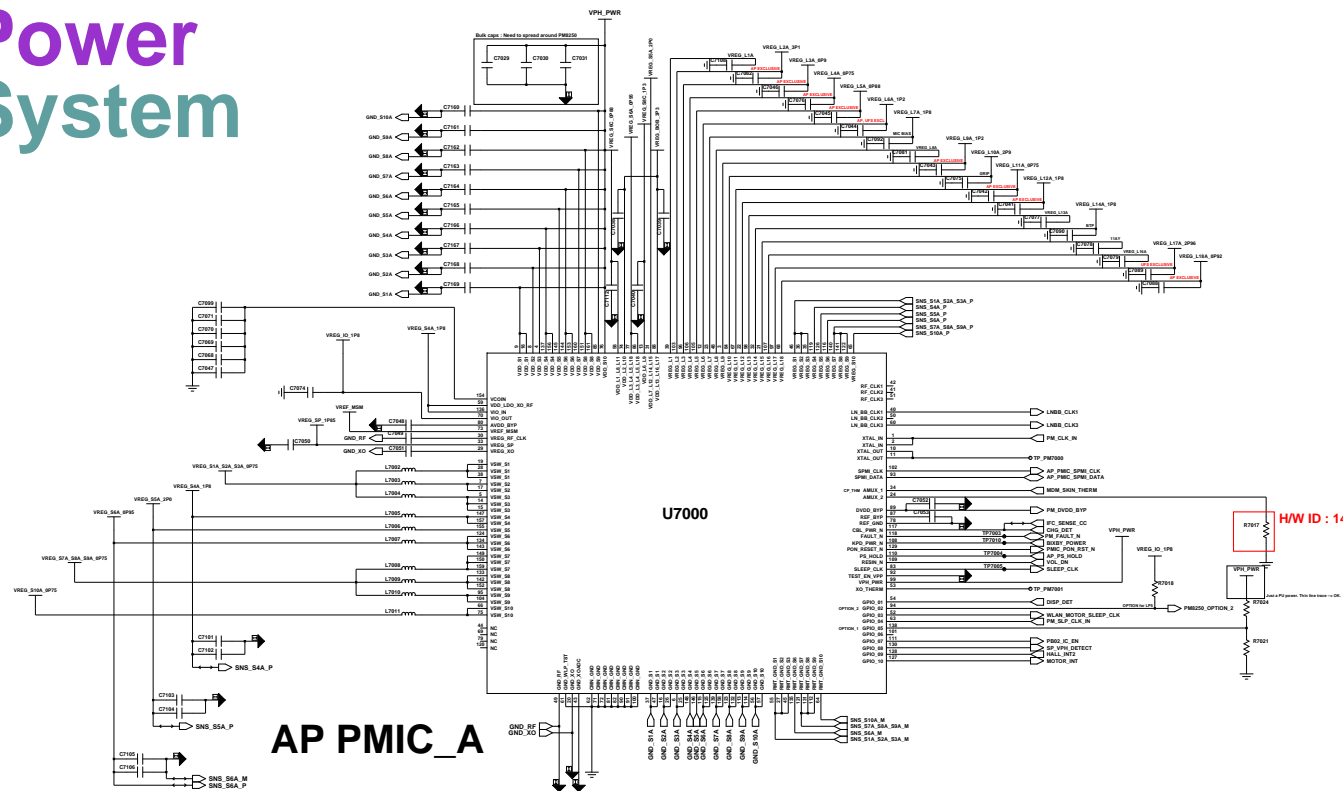


## I2C PULL UP

Engineer	SEC	<div> <div></div> <div> <div></div> <div></div> </div> </div>	
Drawn by:	SEC		
R&D CHK:			
DOC CTRL CHK:			
MFG ENGR CHK:		<div> <div>TITLE:</div> <div>Size:</div> </div>	
		<div>SM8250 + SDX55M</div>	
QA CHK:		Drawing Number	

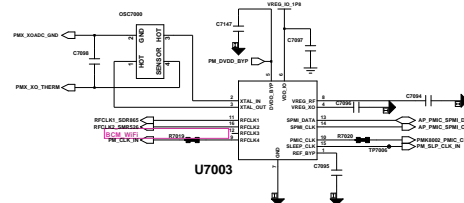


# Power System

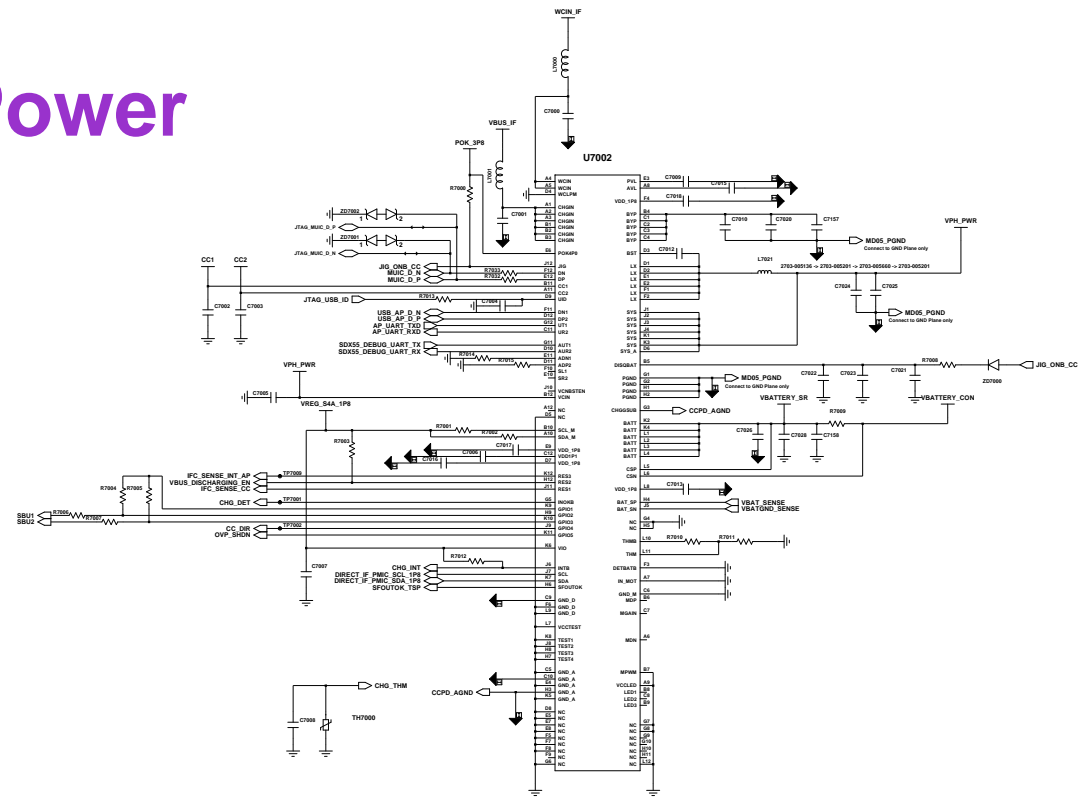


## Clock Generator

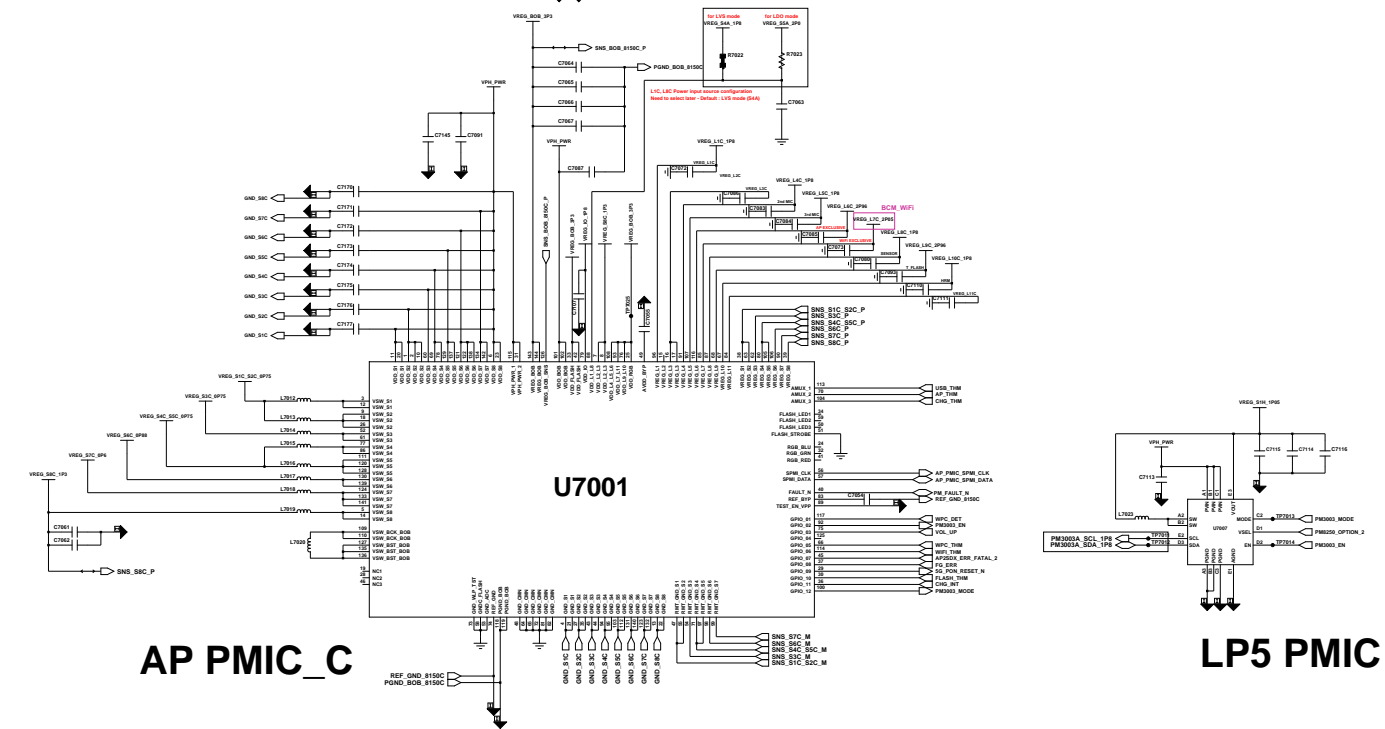
H/W ID table(PM8250 AMUX 2)			
HW ID	BOARD REVISION	Value	Mech
00	SM8250+SDX55M Rev.0	6.04K	
01	SM8250+SDX55M Rev.0.1	9.1K	
02	P2_REV0.0	12.4K	K10
03	P2_REV0.0A	18K	K10
04	P2_REV0.1	22K	K10
05	P2_REV0.1(APIC V2.0 / TRCV V3.0)	30K	
06	SM-G986U_REV0.0(AP V1.0)	39K	K130
07	SM-G986U_REV0.0(P2.0)	47K	K130
08	SM-G986U_REV0.1	56K	K140
09	SM-G986U_REV0.2	68K	K150
10	SM-G986D_REV0.3	82K	YV60
11	SM-G986U_REV0.3	100K	YV60
12	SM-G986U_REV0.3A	129K	YV60
13	SM-G986U/0/WID_REV0.4	150K	YV70
14	SM-G986U_REV0.5	180K	YV80
15		200K	
16		240K	
17		280K	
18		330K	
19		430K	
20		560K	
21		750K	
22		1000K	
23		1500K	
24		3000K	



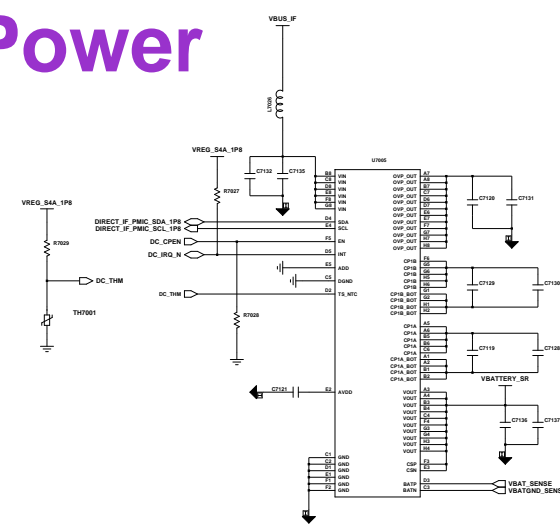
# Power



## IF PMIC (MD05)



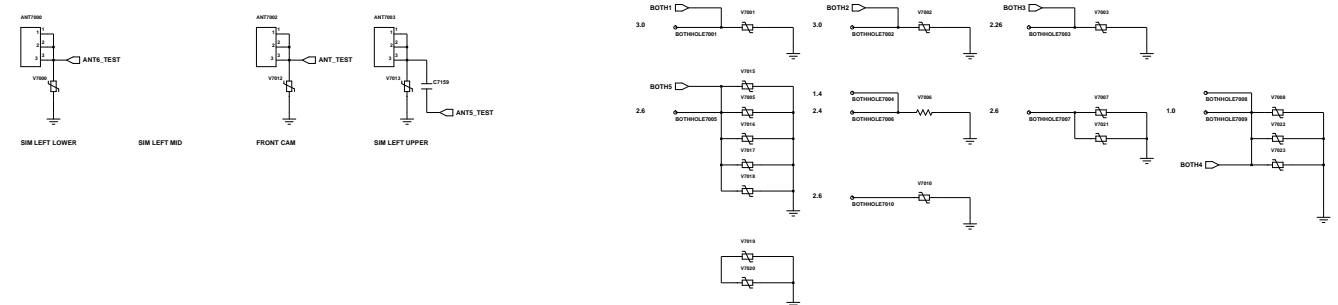
# Power



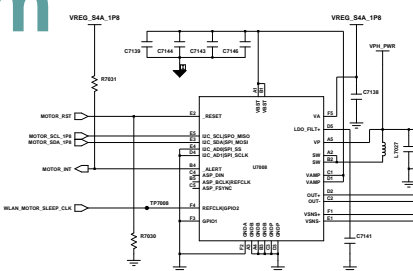
## Direct Charging

## 18W Wireless Charger BQ25910

# SystemRadiation



## Battery Connector



# MOTOR DRV IC

# CCP

## ESD PORON

## BOSS HOLE

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# AUDIO PART

# AUDIO

## SPK AMP

## MAIN MIC

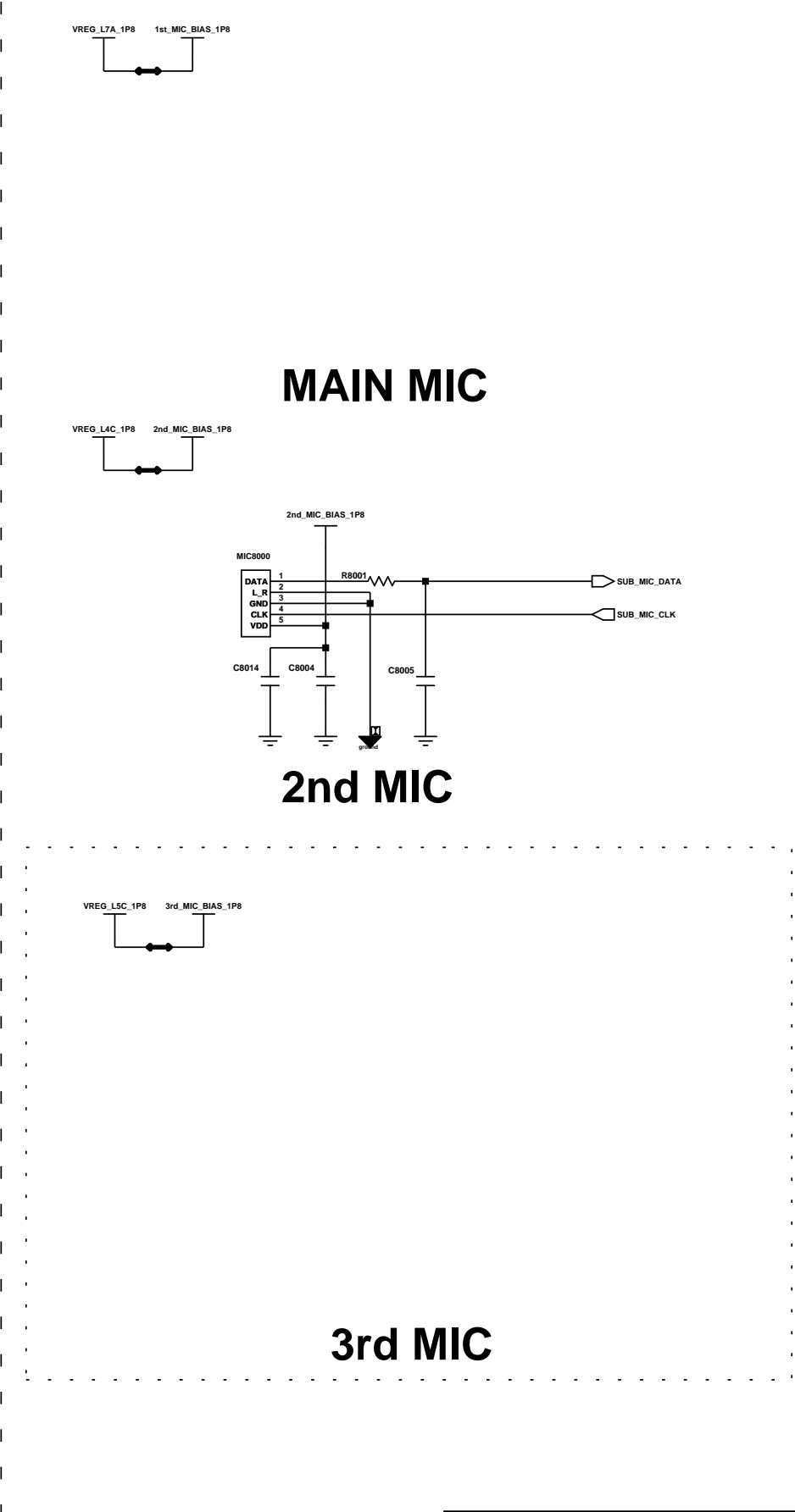
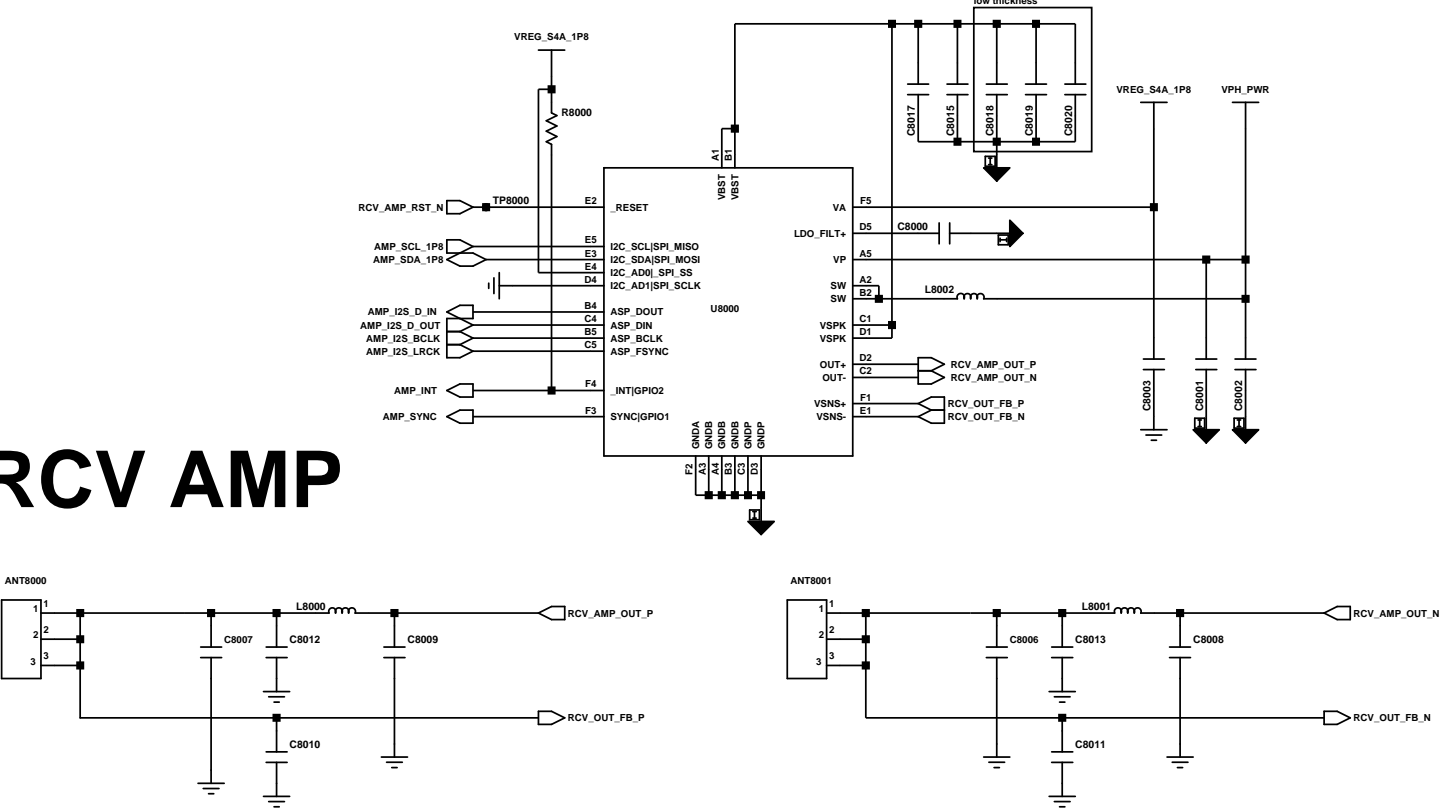
## SPK CONTACT

## 2nd MIC

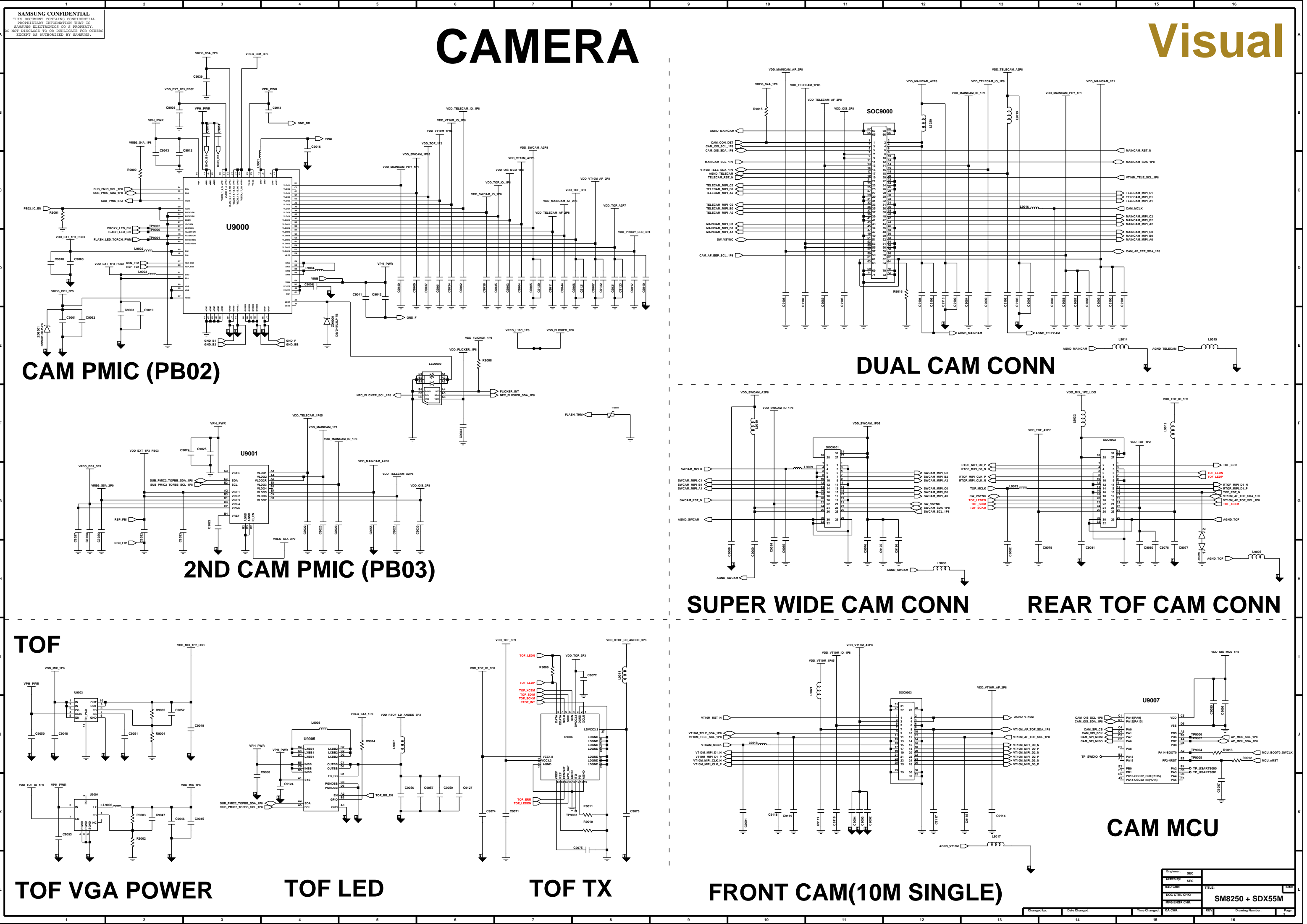
## RCV AMP

## 3rd MIC

## RCV CONTACT

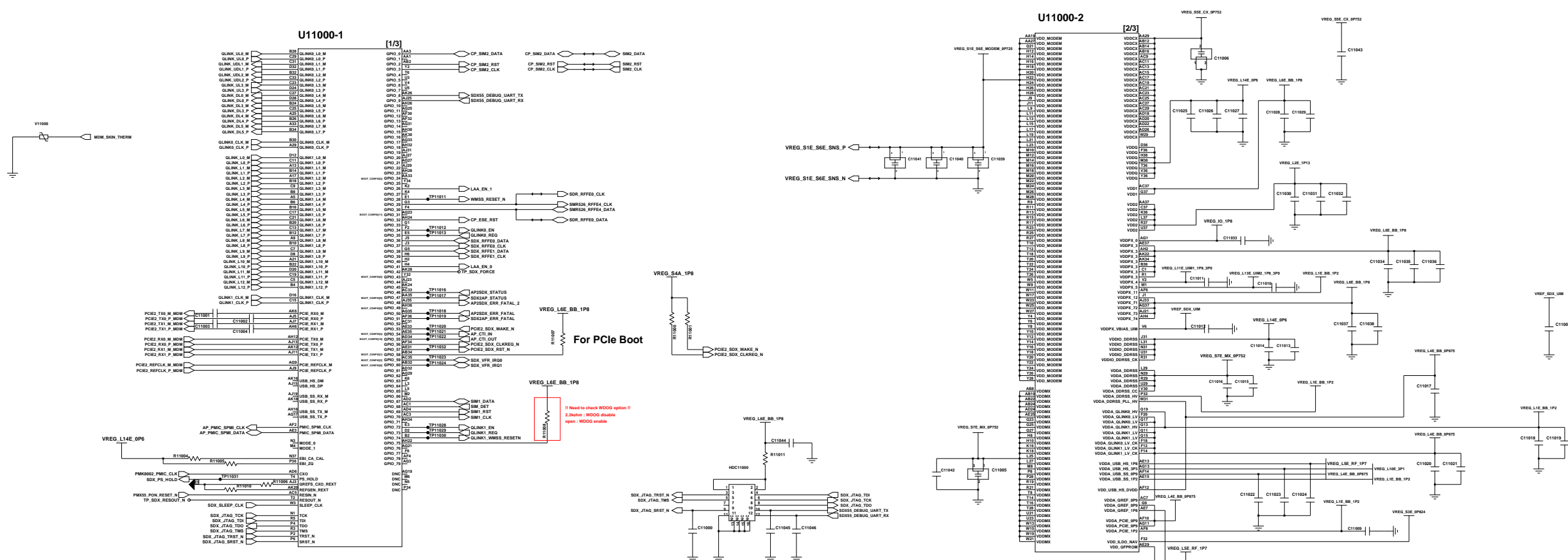




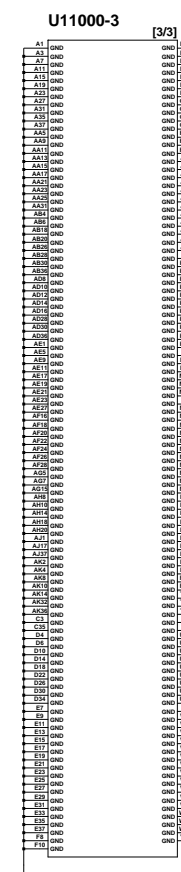




# SDX55M



## JTAG connector for CP



Engineer:	SEC	<div style="text-align: center;"> <b>SAMSUNG</b>  <b>ELECTRONICS</b> </div>		
Drawn by:	SEC			
R&D CHK:		TITLE:	Size:	
DOC CTRL CHK:		<b>SM8250 + SDX55M</b>		
MFG ENGR CHK:				
QA CHK:		REV:	Drawing Number:	Page:



HW ID	BOARD REVISION	Value	Mech
00	SM8250+SDX55M Rev0.0	6.04K	
01		9.1K	
02	P2_REV0.0	12.4K	KI10
03	P2_REV0.0A	18K	KI10
04	P2_REV0.1	22K	KI20
05	P2_REV0.1(AP/CP V2.0 / TRCV V3.0)	30K	
06	SM-G986U_REV0.0(AP V1.0)	39K	KI30
07	SM-G986U_REV0.0(AP V1.0)	47K	KI30
08	SM-G986U_REV0.1	56K	KI40
09	SM-G986U_REV0.1 (QPM6585 NC)	68K	KI40
10	SM-G986U_REV0.1 (QPM6585.8972 NC)	82K	KI40
11	SM-G986U_REV0.2	100K	KI50
12	SM-G986U_REV0.3	120K	VY60
13	SM-G986U_REV0.3A	150K	VY60
14	SM-G986U_REV0.4	180K	VY70
15	SM-G986U_REV0.4 (QAT5515)	200K	VY70
16	SM-G986U_REV0.5	240K	VY75
17	SM-G986U_REV0.5A	280K	VY75
18	SM-G986U_REV0.5A	330K	VY75
19		430K	
20		560K	
21		750K	
22		1000K	
23		1500K	
24		3000K	

# Conduction

# 5G IFIC CAN NC



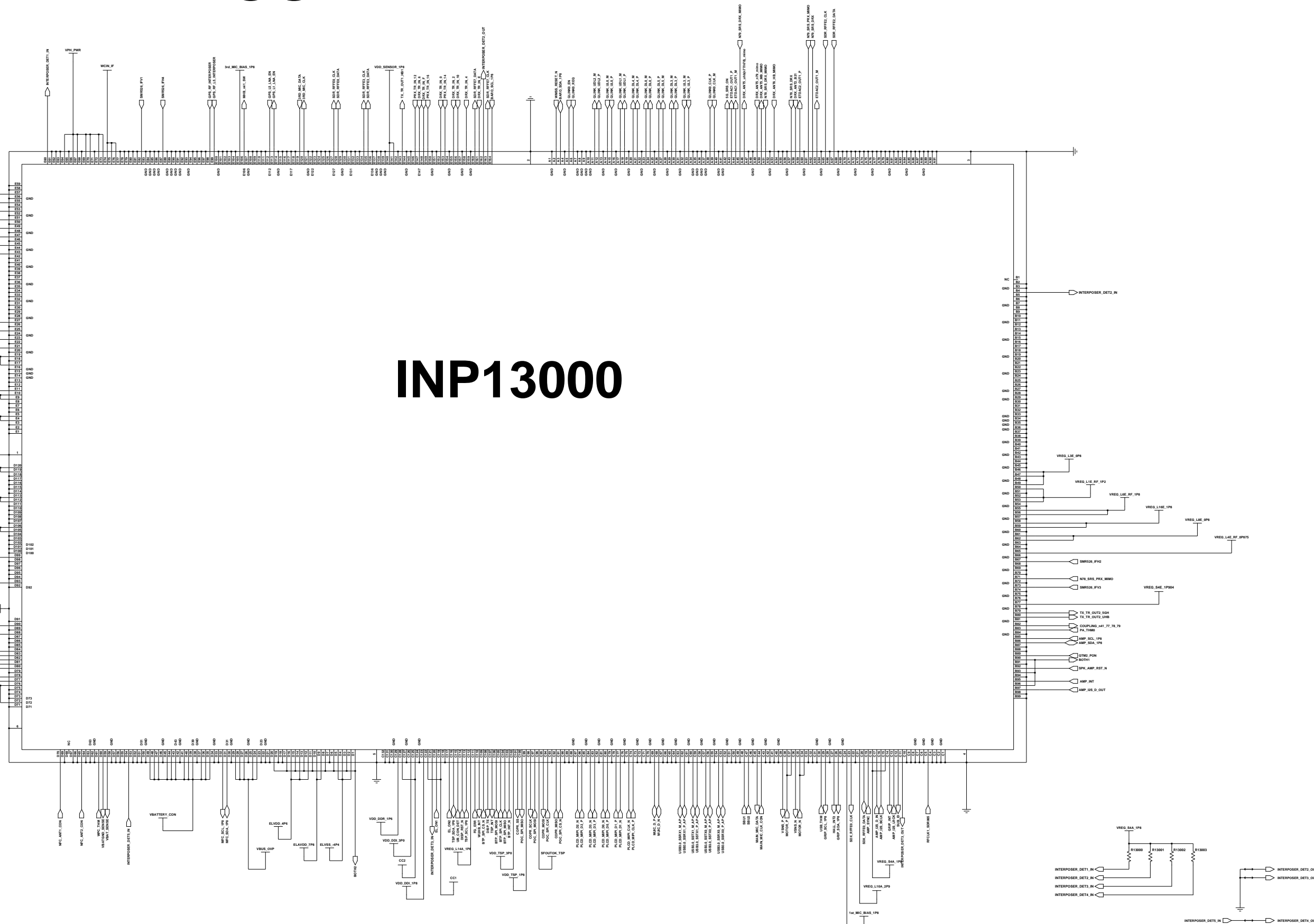
mmW\_ANT\_CONN (Right)



Engineer: SEC	SAMSUNG ELECTRONICS		
Drawn by: SEC			
R&D CHK:	TITLE:		Size:
DOC CTRL CHK:	SM8250 + SDX55M		
MFG ENGR CHK:			
QA CHK:			
	REV:	Drawing Number:	Page:

# INTERPOSER

# INP13000



Engineer:	SEC	<div style="text-align: center;"> <b>SAMSUNG</b>  <b>ELECTRONICS</b> </div>		
Drawn by:	SEC			
R&D CHK:		TITLE:	Size:	
DOC CTRL CHK:		<b>SM8250 + SDX55M</b>		
MFG ENGR CHK:				
QA CHK:		REV:	Drawing Number:	Page:

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	
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																L
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	

# HUBBLE 2 CAN SLAVE REV0.5A

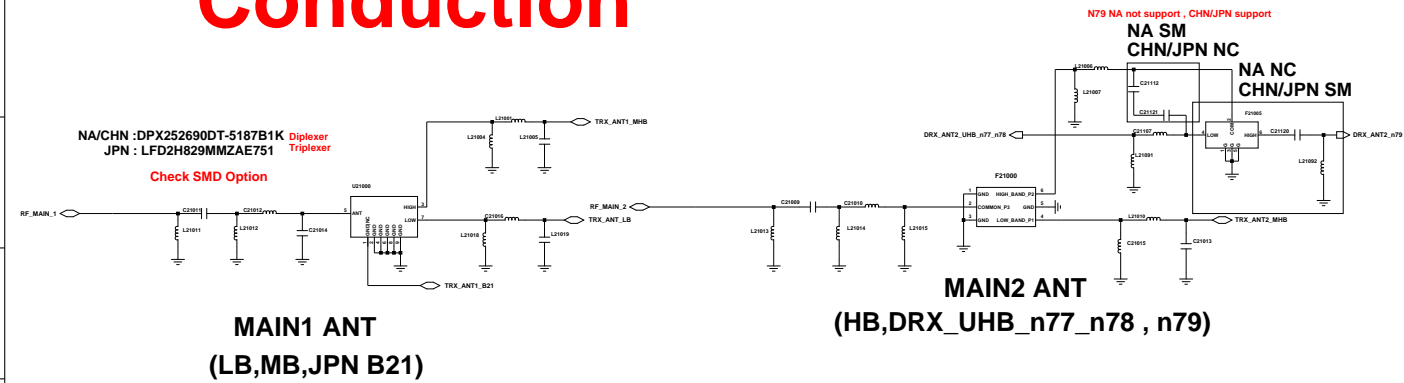
2019. 12.16

METAL Ver(200107)  
0210 change R21004, R21005

- sheet01 : RF (1/2), MMW Conn
- sheet02 : RF (2/2), TRCV\_SDR865
- sheet03 : BT/WIFI, SIM, SHILDCAN
- sheet04 : MFC, MFC Conn, 6XIS, BATT Conn, SPK AMP
- sheet05 : Lower SUB Conn, KEYLESS, DISPLAY Con
- sheet06 : INTERPOSER

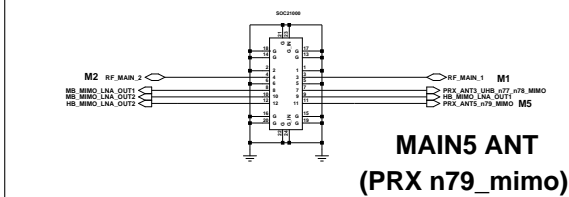
Engineer:			
Drawn by:			
RDG CHK:	TITLE:		Size:
DOC CTRL CHK:			
MFG ENGR CHK:			

# Conduction

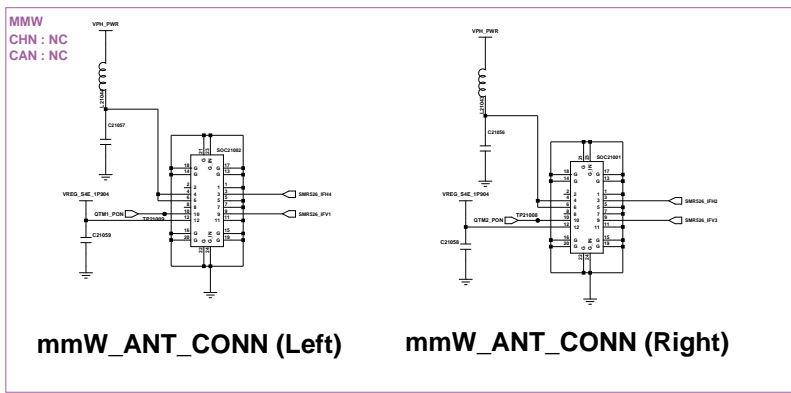


MAIN3 ANT  
( PRX hb MIMO , PRX uhb/n77/n78 mimo )

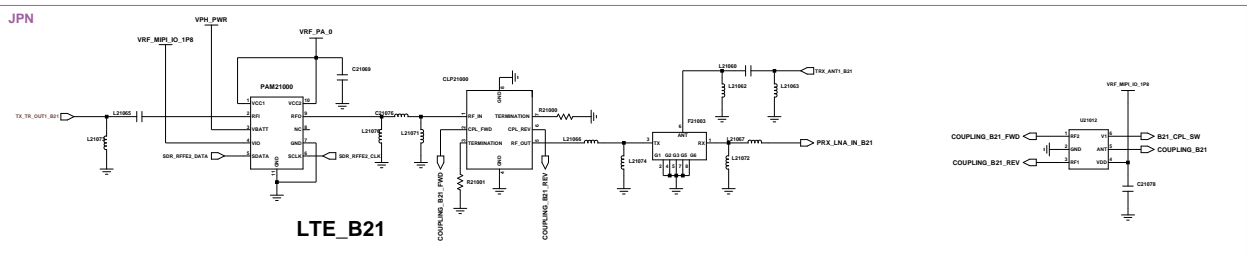
MAIN4 ANT  
( PRX mb MIMO )



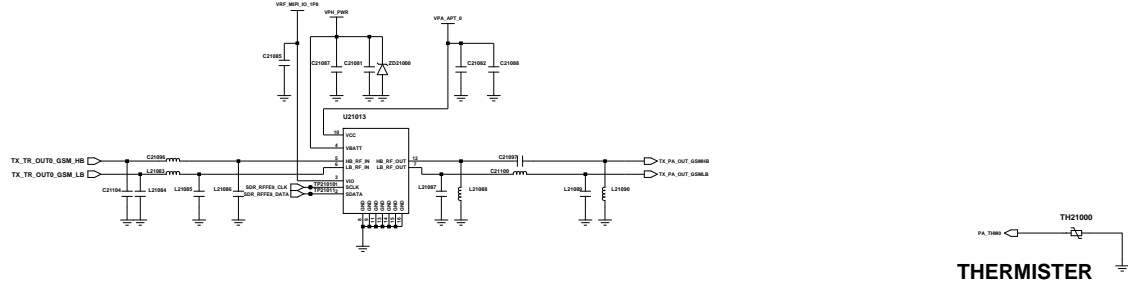
## FRC connector



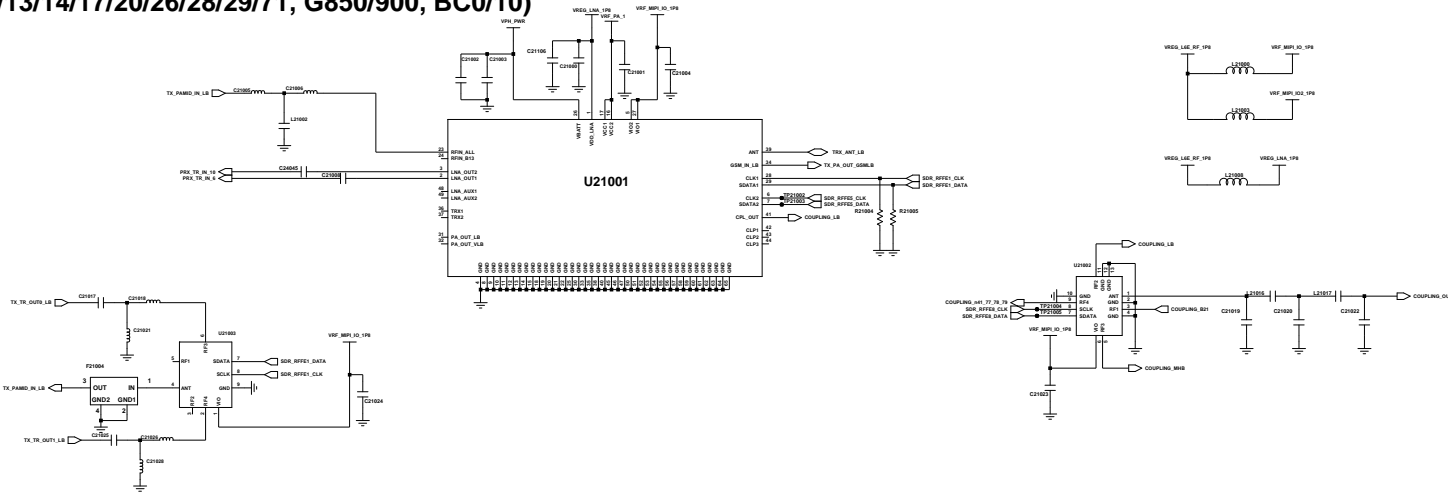
SMD option ( B21 )  
NA / CHN no support  
JPN support



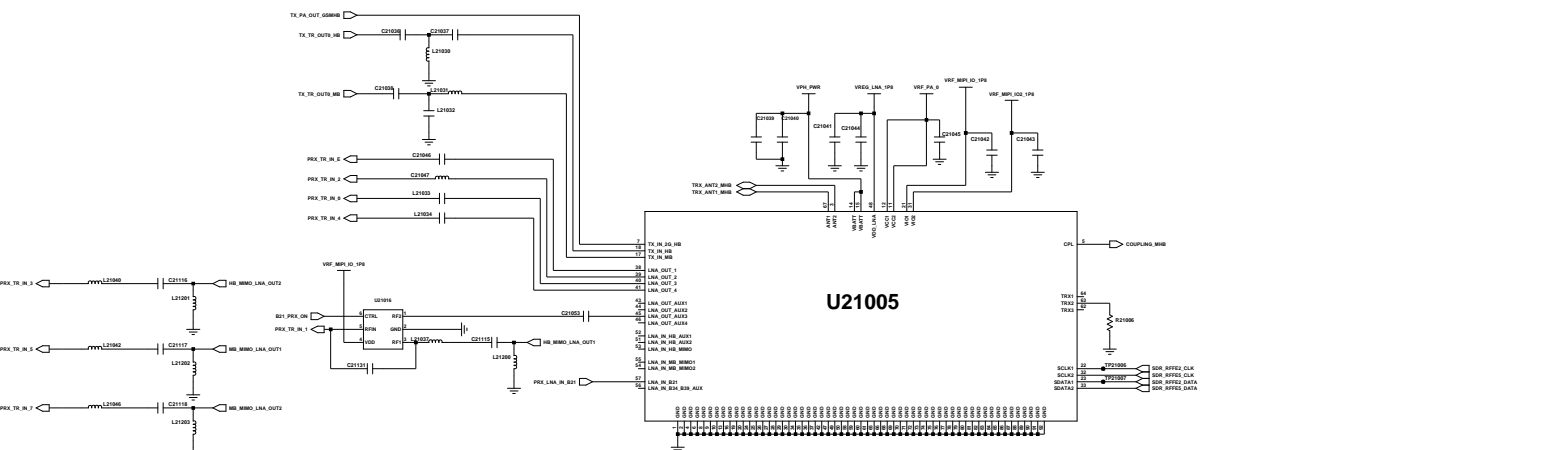
## 2G\_PA



## LB LPAMID (B5/8/12/13/14/17/20/26/28/29/71, G850/900, BC0/10)



## OMH LPAMID (B1/2/3/4/7/25/30/34/38/39/40/41/66, G1800/1900, BC1)

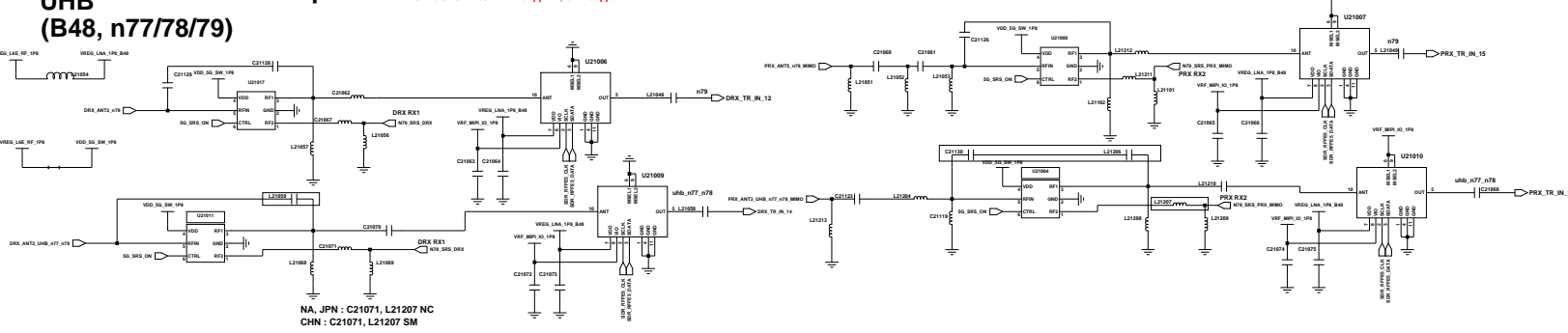


## UHB (B48, n77/78/79)

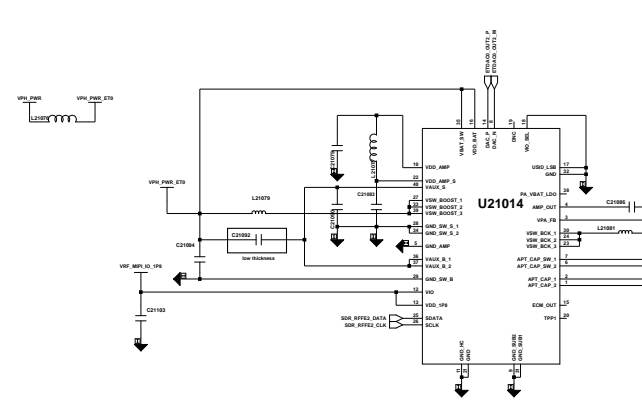
### SMD option

N79 NA not support , CHN/JPN support  
N79N78 SRS NA/JPN not support , CHN support

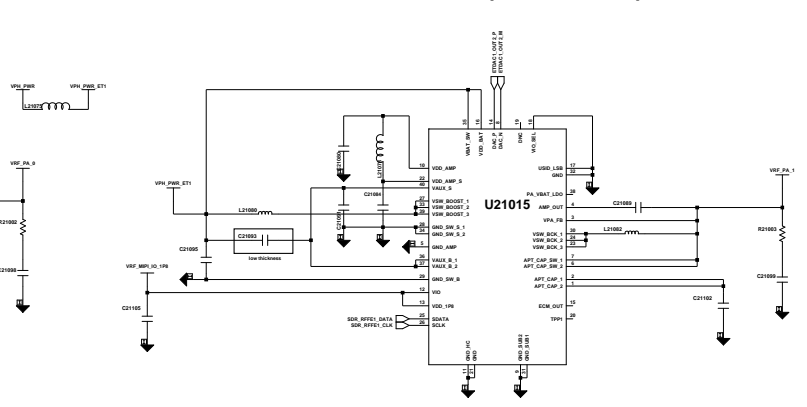
NA , JPN : L21059, C21130, L21206 SM / U21011, U21004 NC  
CHN : L21059, C21130, L21206 NC / U21011, U21004 SM



## ET Modulator(QET5100#0)



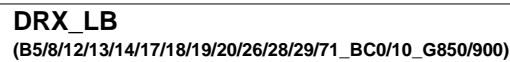
## ET Modulator(QET5100#1)







# GPS\_L1 Connectivity



# Conduction

**DRX\_MHB\_1**  
(B1/2/3/4/7/25/30/39/41/66\_BC1\_DCS/PCS)

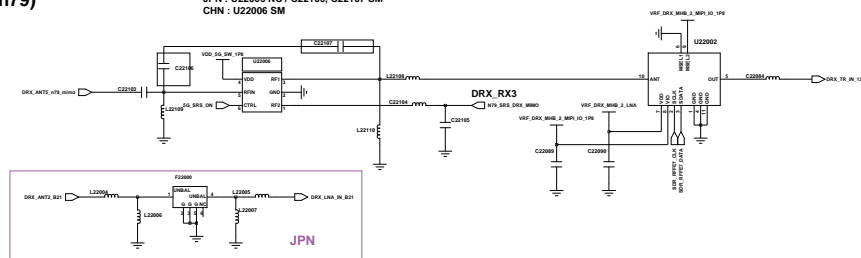


**DRX\_MHB\_2**  
(B2/4/7/25/30/41/66)



N79 NA not support , CHN/JPN support  
N79 SRS NA/JPN not support , CHN support

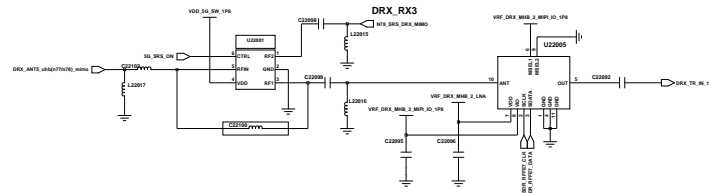
JPN : U22006 NC / C22106, C22107  
CHN : U22006 SM



**UHB**  
(B48, n77/78)

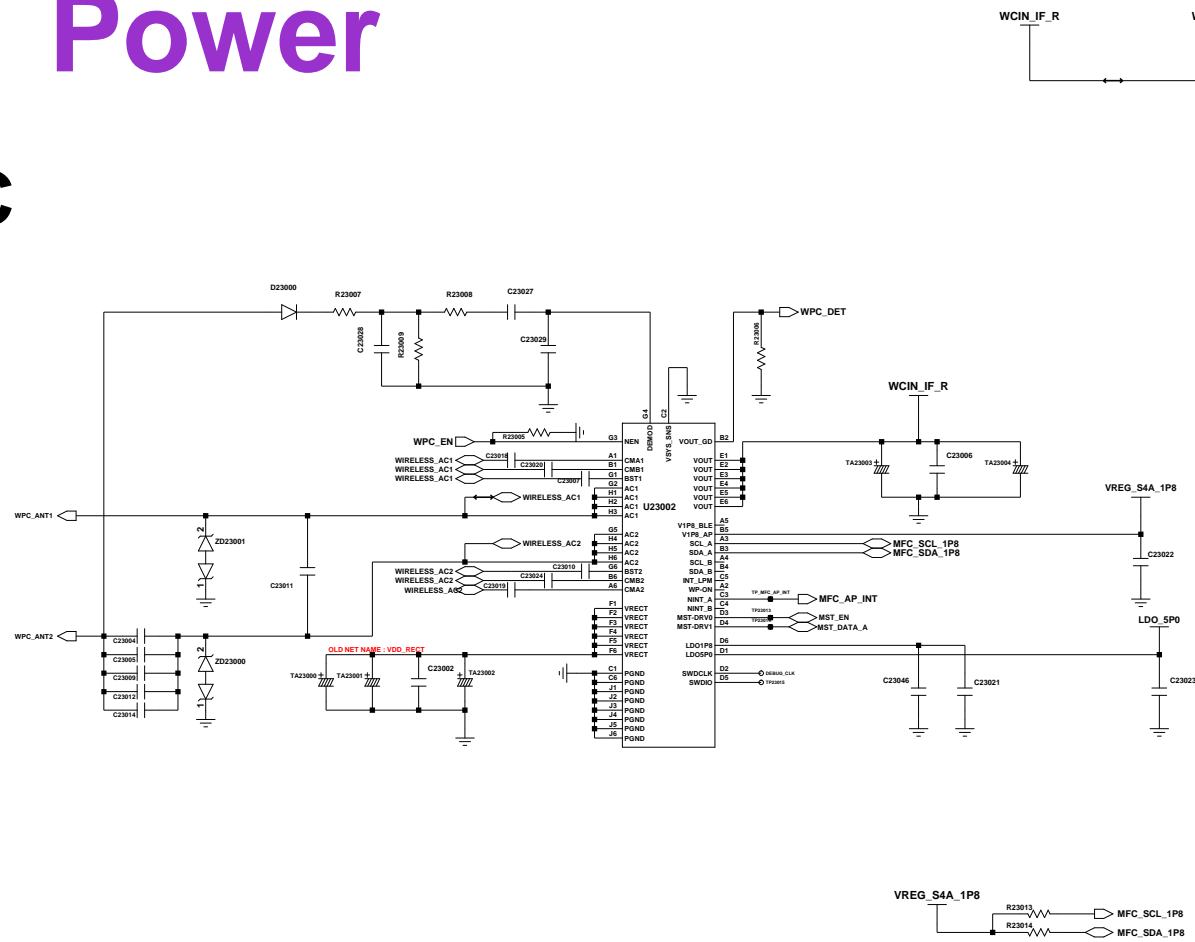
N78 SRS NA/JPN not support , CHN support

**SRS - 1T4R**  
(n77/78)

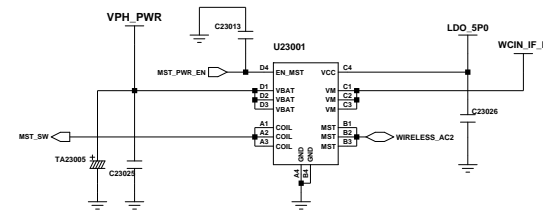


Engineer:	SEC	TITLE:  <b>SM8250 + SDX55M</b>
Drawn by:	SEC	
Read Check:		
ISO Check:		

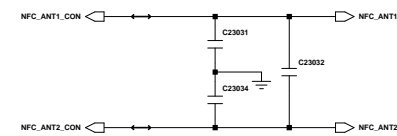
# MFC



## MST Switch

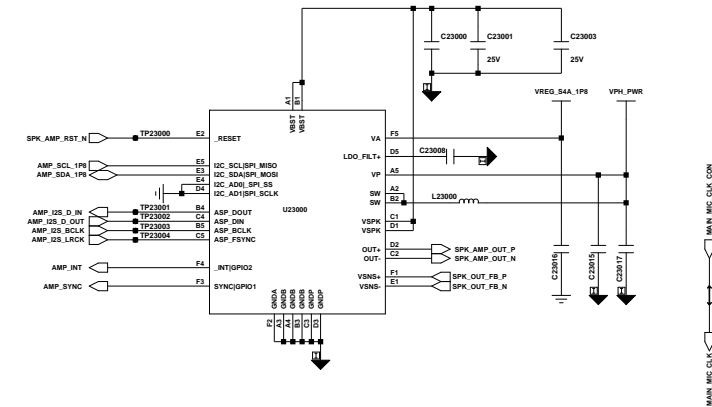


# NFC

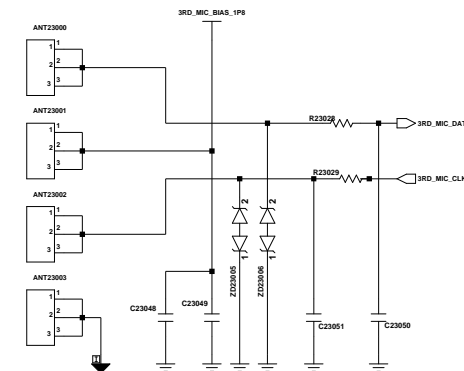


# SPK AMP

# AUDIO



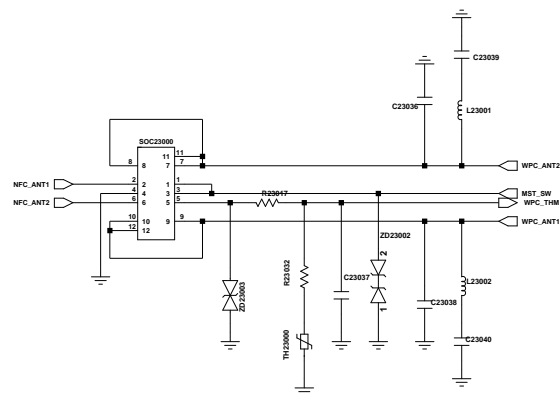
### 3rd MIC



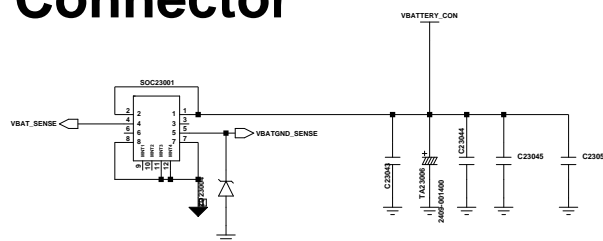
# Visual



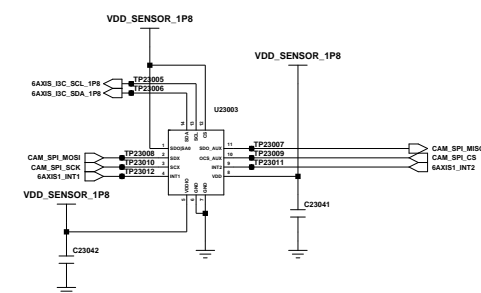
## W/C CONNECTOR



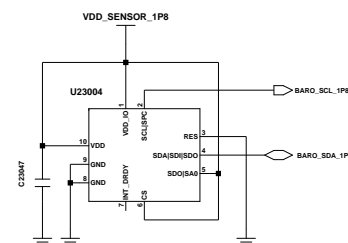
## Battery Connector



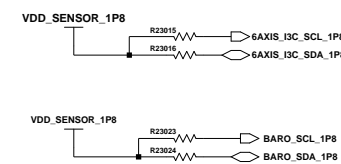
# Power



# SENSORS

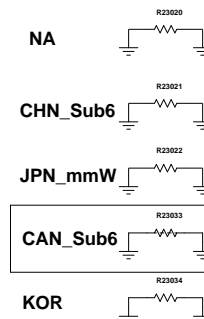
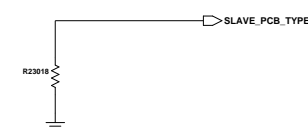


## 6 Axis SENSOR (GYRO,ACCEL)



# System

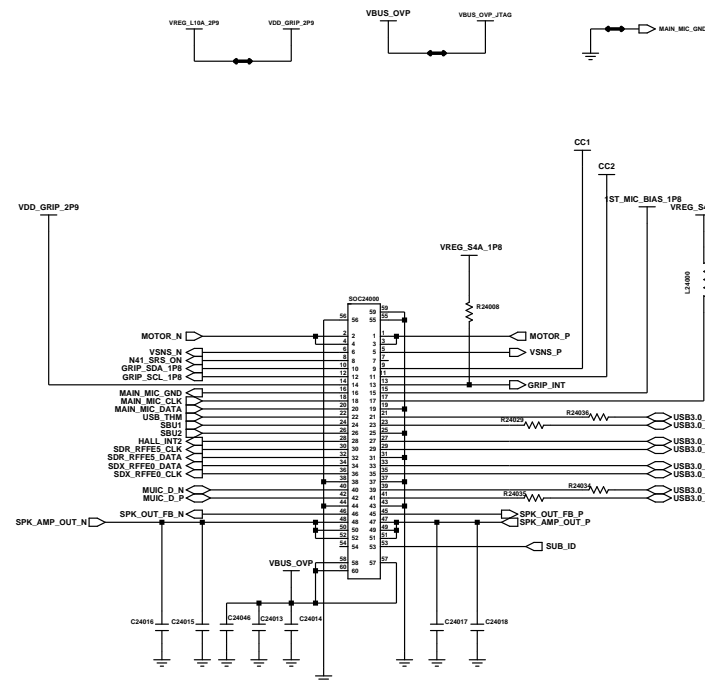
SLAVE_TYPE	
	ADC
NA_Sub6_mmW(G986U)	68K
NA_CAN_Sub6(G986W)	100K
CHN_Sub6(G986D)	150K
LA_LTE	200K
KOR_Sub6(G956N)	270K
MEA_LTE	430K
JPN_mmW(G986D)	750K
JPN_LTE	1500K
For JIG	OPEN



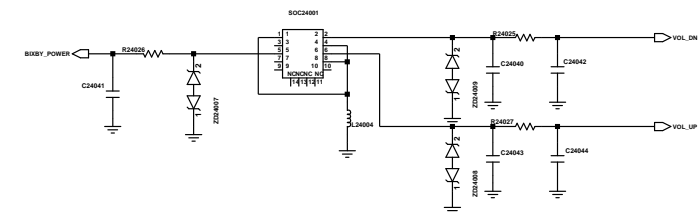
Engineer:	SEC	<div><div>TITLE:</div><div>Size:</div><div>SM8250 + SDX55M</div><div>16 1/2"</div></div>	
Drawn by:	SEC		
R&D CHK:			
DOC CTRL CHK:			
MFG ENGR CHK:			
QA CHK:	REV:	Drawing Number:	Page:

# System

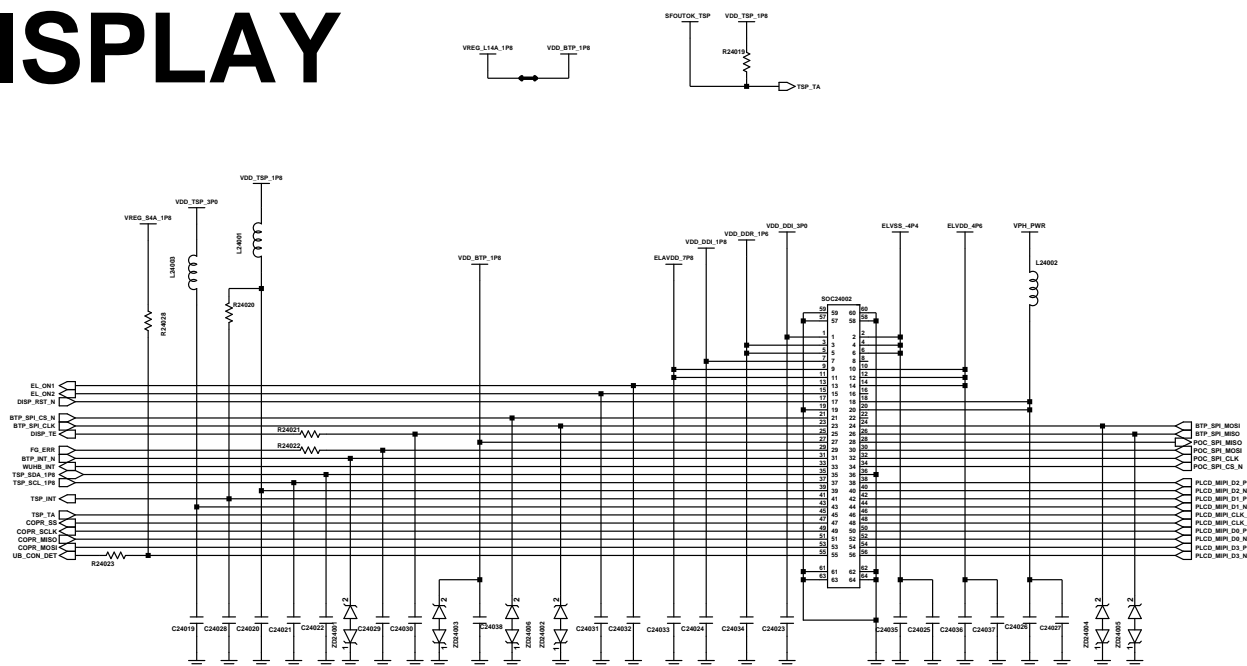
## Lower SUB Conn



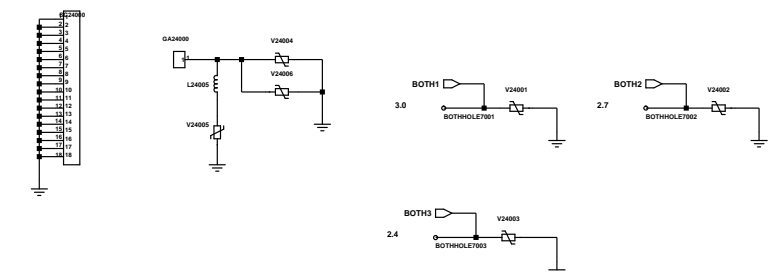
# Vol key



# Visual DISPLAY



# Design



## SHIELD CAN

## BOSS HOLE

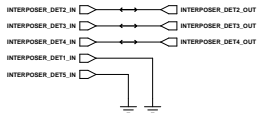
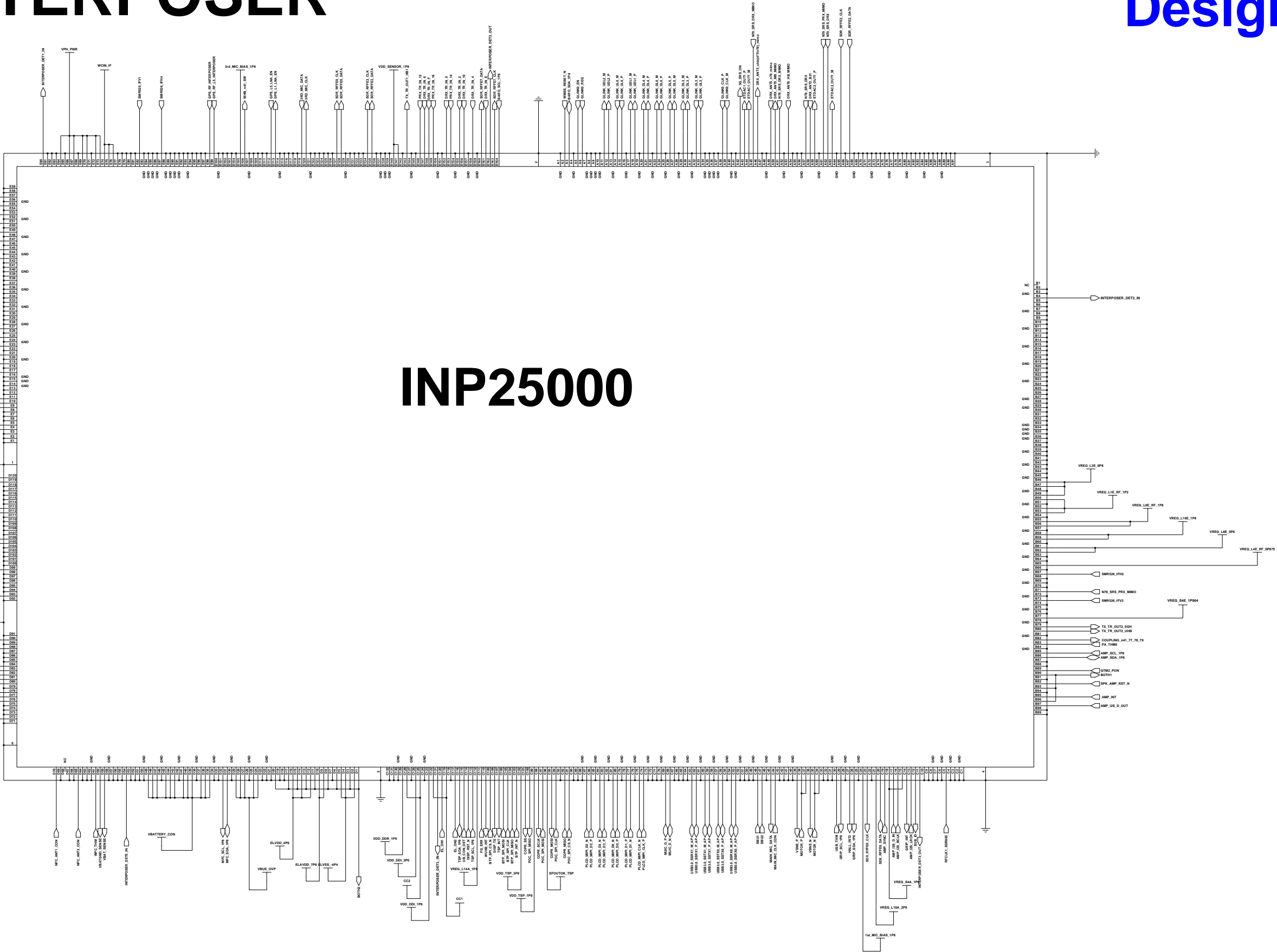
## 2D BACODE

Engineer:	SEC	<div style="text-align: center;"> <b>SAMSUNG</b>  <b>ELECTRONICS</b> </div>		
Drawn by:	SEC			
R&D CHK:		TITLE:	<div style="text-align: center;"> <b>SM8250 + SDX55M</b> </div>	
DOC CTRL CHK:				
MFG ENGR CHK:				
QA CHK:		REV:	Drawing Number:	Page:

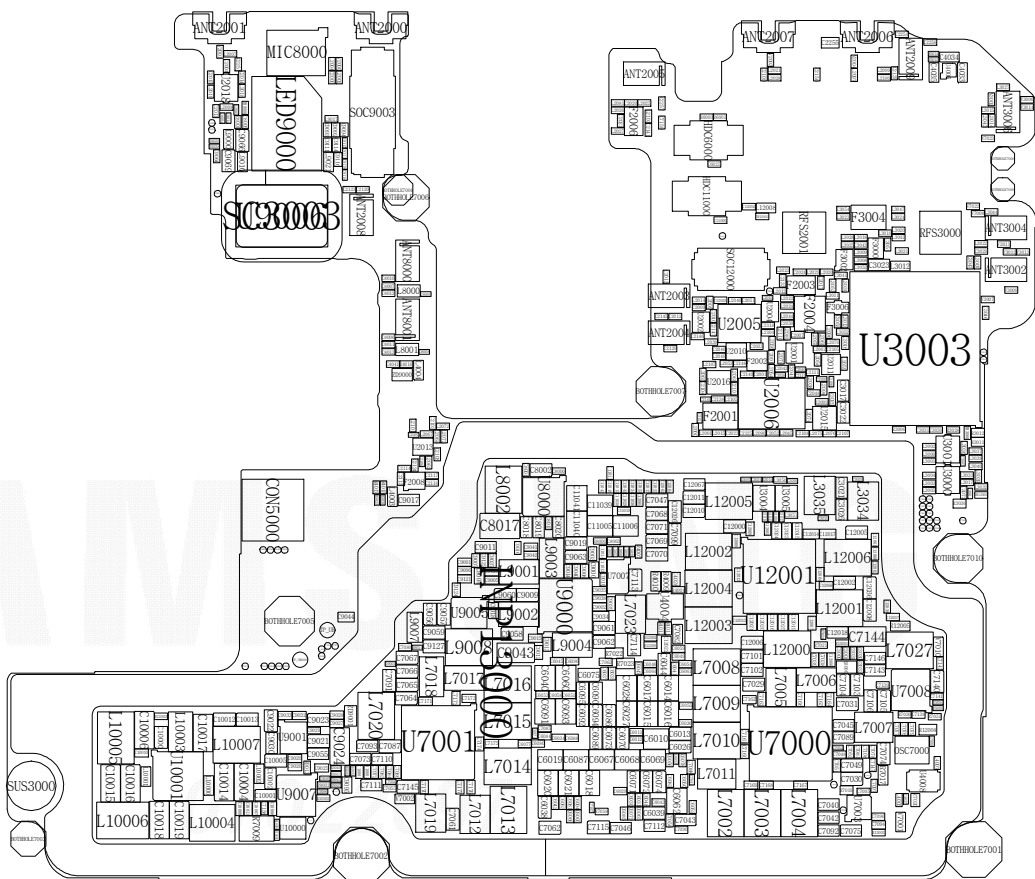
# INTERPOSER

# Design

## INP25000



Engineer:	SEC	SAMSUNG ELECTRONICS	
Drawn by:	SEC		
R&D CHK:		TITLE:	Size:
DOC CTRL CHK:		SM8250 + SDX55M	
MFG ENGR CHK:			
Changed by:	Date Changed:	Time Changed:	QA CHK:
100	Thursday, December 1, 2016	3:17:21 pm	
Drawing Number:		Page:	
		14	



JTAG6001

